DS05-20862-3E

### FLASH MEMORY

**CMOS** 

# 4M (512K $\times$ 8/256K $\times$ 16) BIT

### MBM29LV400TC-70/-90/-12/MBM29LV400BC-70/-90/-12

#### **■ FEATURES**

• Single 3.0 V read, program, and erase

Minimizes system level power requirements

Compatible with JEDEC-standard commands

Uses same software commands as E2PROMs

• Compatible with JEDEC-standard world-wide pinouts

48-pin TSOP(I) (Package suffix: PFTN - Normal Bend Type, PFTR - Reversed Bend Type)

44-pin SOP (Package suffix: PF)

48-pin CSOP (Package suffix: PCV)

48-ball FBGA (Package suffix: PBT)

- Minimum 100,000 program/erase cycles
- High performance

70 ns maximum access time

· Sector erase architecture

One 8K word, two 4K words, one 16K word, and seven 32K words sectors in word mode One 16K byte, two 8K bytes, one 32K byte, and seven 64K bytes sectors in byte mode Any combination of sectors can be concurrently erased. Also supports full chip erase

• Boot Code Sector Architecture

T = Top sector

B = Bottom sector

Embedded Erase<sup>™</sup> Algorithms

Automatically preprograms and erases the chip or any sector

• Embedded Program™ Algorithms

Automatically writes and verifies data at specified address

- Data Polling and Toggle Bit feature for detection of program or erase cycle completion
- Ready/Busy output (RY/BY)

Hardware method for detection of program or erase cycle completion

Automatic sleep mode

When addresses remain stable, automatically switch themselves to low power mode

- Low Vcc write inhibit ≤ 2.5 V
- Erase Suspend/Resume

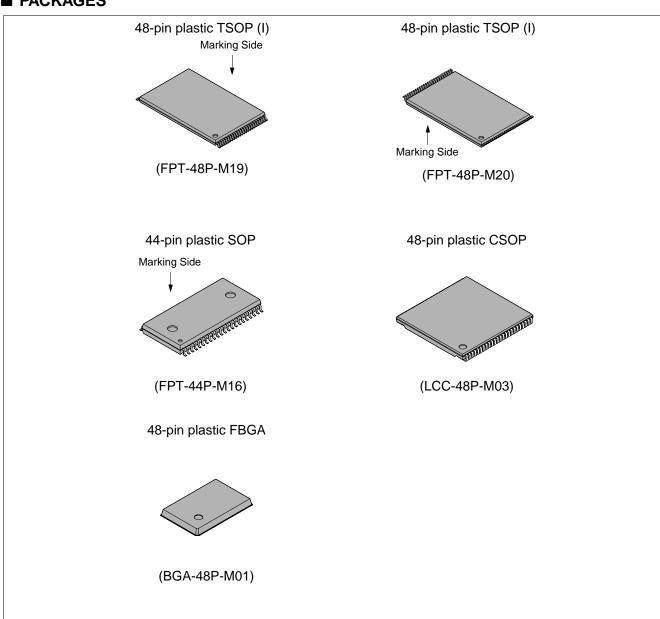
Suspends the erase operation to allow a read in another sector within the same device

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- Sector protection
  - Hardware method disables any combination of sectors from program or erase operations
- Sector Protection set function by Extended sector Protect command
- Temporary sector unprotection
  - Temporary sector unprotection via the RESET pin

#### **■ PACKAGES**



#### **■** GENERAL DESCRIPTION

The MBM29LV400TC/BC are a 8M-bit, 3.0 V-only Flash memory organized as 512K bytes of 8 bits each or 256K words of 16 bits each. The MBM29LV400TC/BC are offered in a 48-pin TSOP(I), 44-pin SOP, 48-pin CSOP, and 48-ball FBGA packages. These devices are designed to be programmed in-system with the standard system 3.0 V Vcc supply. 12.0 V VPP and 5.0 V Vcc are not required for write or erase operations. The devices can also be reprogrammed in standard EPROM programmers.

The standard MBM29LV400TC/BC offer access times 70 ns and 120 ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention the devices have separate chip enable  $(\overline{CE})$ , write enable  $(\overline{WE})$ , and output enable  $(\overline{OE})$  controls.

The MBM29LV400TC/BC are pin and command set compatible with JEDEC standard E²PROMs. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the devices is similar to reading from 5.0 V and 12.0 V Flash or EPROM devices.

The MBM29LV400TC/BC are programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margin. Typically, each sector can be programmed and verified in about 0.5 seconds. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the devices automatically time the erase pulse widths and verify proper cell margin.

A sector is typically erased and verified in 1.0 second. (If already completely preprogrammed.)

The devices also feature a sector erase architecture. The sector mode allows each sector to be erased and reprogrammed without affecting other sectors. The MBM29LV400TC/BC are erased when shipped from the factory.

The devices feature single 3.0 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. A low  $V_{CC}$  detector automatically inhibits write operations on the loss of power. The end of program or erase is detected by  $\overline{Data}$  Polling of  $DQ_7$ , by the Toggle Bit feature on  $DQ_6$ , or the RY/ $\overline{BY}$  output pin. Once the end of a program or erase cycle has been completed, the devices internally reset to the read mode.

Fujitsu's Flash technology combines years of EPROM and E²PROM experience to produce the highest levels of quality, reliability, and cost effectiveness. The MBM29LV400TC/BC memories electrically erase the entire chip or all bits within a sector simultaneously via Fowler-Nordhiem tunneling. The bytes/words are programmed one byte/word at a time using the EPROM programming mechanism of hot electron injection.

#### **■ FLEXIBLE SECTOR-ERASE ARCHITECTURE**

- One 16K byte, two 8K bytes, one 32K byte, and seven 64K bytes.
- Individual-sector, multiple-sector, or bulk-erase capability.
- Individual or multiple-sector protection is user definable.

	(×8)	(×16)
	7FFFFH	3FFFFH
16K byte	7BFFFH	3DFFFH
8K byte		
8K byte	79FFFH	3CFFFH
	77FFFH	3BFFFH
32K byte	6FFFFH	37FFFH
64K byte		
64K byte	5FFFFH	2FFFFH
	4FFFFH	27FFFH
64K byte	3FFFFH	1FFFFH
64K byte	2FFFFH	475551
64K byte	2FFFF	17FFFH
64K byto	1FFFFH	0FFFFH
64K byte	0FFFFH	07FFFH
64K byte	00000	00000H
	00000H	00000H

	7FFFFH	3FFFFH
64K byte	6FFFFH	37FFFH
64K byte		
64K byte	5FFFFH	2FFFFH
64K byte	4FFFFH	27FFFH
,	3FFFFH	1FFFFH
64K byte	2FFFFH	17FFFH
64K byte	1FFFFH	0FFFFH
64K byte		
32K byte	0FFFFH	07FFFH
8K byte	07FFFH	03FFFH
	05FFFH	02FFFH
8K byte	03FFFH	01FFFH
16K byte	00000H	00000H
	0000011	0000011

(×8)

(×16)

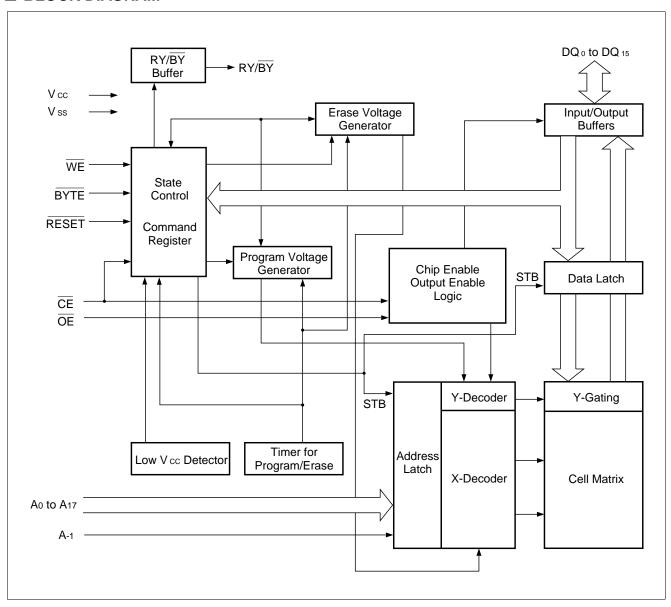
MBM29LV400TC Sector Architecture

MBM29LV400BC Sector Architecture

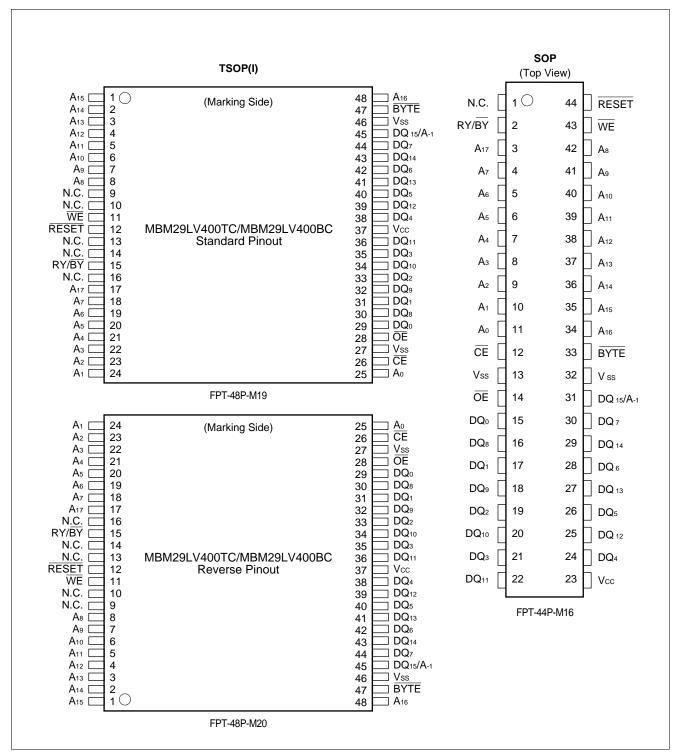
#### **■ PRODUCT LINE UP**

Part N	0.	MBM29LV400TC/MBM29LV400BC							
Ordering Part No.	$Vcc = 3.3 \text{ V} \begin{array}{c} +0.3 \text{ V} \\ -0.3 \text{ V} \end{array}$	-70	_	_					
Ordering Fart No.	$Vcc = 3.0 \text{ V} ^{+0.6 \text{ V}}_{-0.3 \text{ V}}$	_	-90	-12					
Max. Address Access T	īme (ns)	70	90	120					
Max. CE Access Time (ns)		70	90	120					
Max. OE Access Time	(ns)	30	35	50					

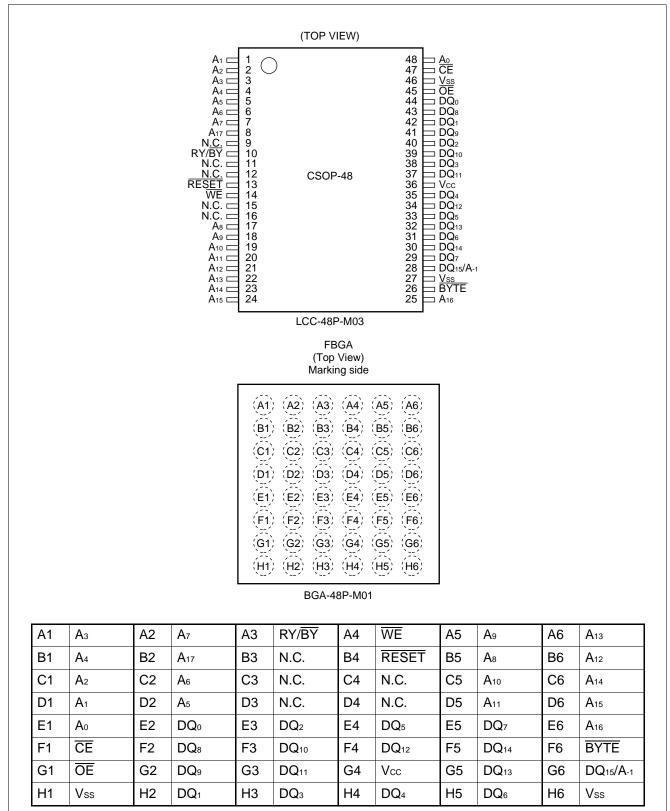
#### **■ BLOCK DIAGRAM**



#### **■ CONNECTION DIAGRAMS**



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#### **■ LOGIC SYMBOL**

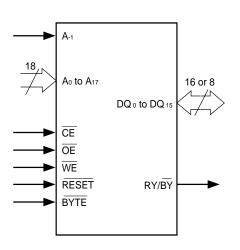


Table 1 MBM29LV400TC/400BC Pin Configuration

Pin	Function
A-1, A <sub>0</sub> to A <sub>17</sub>	Address Inputs
DQ <sub>0</sub> to DQ <sub>15</sub>	Data Inputs/Outputs
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
RY/BY	Ready/Busy Output
RESET	Hardware Reset Pin/Temporary Sector Unprotection
BYTE	Selects 8-bit or 16-bit mode
N.C.	No Internal Connection
Vss	Device Ground
Vcc	Device Power Supply

Table 2 MBM29LV400TC/400BC User Bus Operations (BYTE = VIH)

Operation	CE	ŌĒ	WE	Ao	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	DQ <sub>0</sub> to DQ <sub>15</sub>	RESET
Auto-Select Manufacturer Code (1)	L	L	Н	L	L	L	VID	Code	Н
Auto-Select Device Code (1)	L	L	Н	Η	L	L	VID	Code	Н
Read (3)	L	L	Н	Ao	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	<b>D</b> оит	Н
Standby	Н	Х	Х	Χ	Χ	Х	Х	HIGH-Z	Н
Output Disable	L	Н	Н	Χ	Χ	Х	Х	HIGH-Z	Н
Write (Program/Erase)	L	Н	L	A <sub>0</sub>	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	Din	Н
Enable Sector Protection (2), (4)	L	VID	T	L	Н	L	VID	Х	Н
Verify Sector Protection (2), (4)	L	L	Н	L	Н	L	VID	Code	Н
Temporary Sector Unprotection	Х	Х	Х	Χ	Х	Х	Χ	Х	VID
Reset (Hardware)/Standby	Х	Х	Х	Χ	Χ	Х	Х	HIGH-Z	L

Table 3 MBM29LV400TC/400BC User Bus Operations ( $\overline{BYTE} = V_{IL}$ )

Operation	CE	ŌĒ	WE	DQ <sub>15</sub> / A-1	Ao	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	DQ <sub>0</sub> to DQ <sub>7</sub>	RESET
Auto-Select Manufacturer Code (1)	L	L	Н	L	L	L	L	VID	Code	Н
Auto-Select Device Code (1)	L	L	Н	L	Н	L	L	VID	Code	Н
Read (3)	L	L	Н	<b>A</b> -1	<b>A</b> 0	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	<b>D</b> оит	Н
Standby	Н	Х	Х	Х	Х	Х	Х	Х	HIGH-Z	Н
Output Disable	L	Н	Н	Х	Х	Х	Х	Х	HIGH-Z	Н
Write (Program/Erase)	L	Н	L	<b>A</b> -1	<b>A</b> 0	<b>A</b> 1	<b>A</b> 6	<b>A</b> 9	Din	Н
Enable Sector Protection (2), (4)	L	VID	T	L	L	Н	L	VID	Х	Н
Verify Sector Protection (2), (4)	L	L	Н	L	L	Н	L	VID	Code	Н
Temporary Sector Unprotection (5)	Х	Х	Х	Х	Х	Х	Х	Х	Х	VID
Reset (Hardware)/Standby	Χ	Х	Х	Х	Χ	Х	Х	Х	HIGH-Z	L

**Legend:** L =  $V_{IL}$ , H =  $V_{IH}$ , X =  $V_{IL}$  or  $V_{IH}$ ,  $\Box \Box \Box$  = Pulse input. See DC Characteristics for voltage levels.

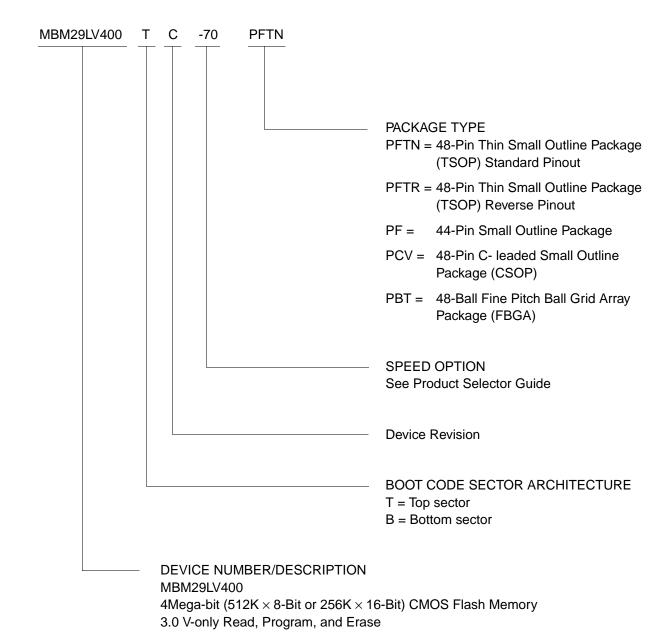
**Notes:** 1. Manufacturer and device codes may also be accessed via a command register write sequence. See Table 7.

- 2. Refer to the section on Sector Protection.
- 3.  $\overline{\text{WE}}$  can be  $V_{\text{IL}}$  if  $\overline{\text{OE}}$  is  $V_{\text{IL}}$ ,  $\overline{\text{OE}}$  at  $V_{\text{IH}}$  initiates the write operations.
- 4.  $Vcc = 3.3 V \pm 10\%$
- 5. It is also used for the extended sector protection.

#### **■** ORDERING INFORMATION

#### **Standard Products**

Fujitsu standard products are available in several packages. The order number is formed by a combination of:



#### **■ FUNCTIONAL DESCRIPTION**

#### **Read Mode**

The MBM29LV400TC/BC have two control functions which must be satisfied in order to obtain data at the outputs.  $\overline{\text{CE}}$  is the power control and should be used for a device selection.  $\overline{\text{OE}}$  is the output control and should be used to gate data to the output pins if a device is selected.

Address access time (tacc) is equal to the delay from stable addresses to valid output data. The chip enable access time (tce) is the delay from stable addresses and stable  $\overline{CE}$  to valid data at the output pins. The output enable access time is the delay from the falling edge of  $\overline{OE}$  to valid data at the output pins. (Assuming the addresses have been stable for at least tacc-toe time.) When reading out a data without changing addresses after power-up, it is necessary to input hardware reset or change  $\overline{CE}$  pin from "H" or "L"

#### Standby Mode

There are two ways to implement the standby mode on the MBM29LV400TC/BC devices, one using both the  $\overline{\text{CE}}$  and  $\overline{\text{RESET}}$  pins; the other via the  $\overline{\text{RESET}}$  pin only.

When using both pins, a CMOS standby mode is achieved with  $\overline{\text{CE}}$  and  $\overline{\text{RESET}}$  inputs both held at  $Vcc \pm 0.3 \text{ V}$ . Under this condition the current consumed is less than 5  $\mu$ A. The device can be read with standard access time (tce) from either of these standby modes. During Embedded Algorithm operation, Vcc active current (tce) is required even  $\overline{\text{CE}} = \text{"H"}$ .

When using the  $\overline{RESET}$  pin only, a CMOS standby mode is achieved with  $\overline{RESET}$  input held at Vss  $\pm$  0.3 V ( $\overline{CE}$  = "H" or "L"). Under this condition the current is consumed is less than 5  $\mu$ A. Once the  $\overline{RESET}$  pin is taken high, the device requires transfer of wake up time before outputs are valid for read access.

In the standby mode the outputs are in the high impedance state, independent of the  $\overline{OE}$  input.

#### **Automatic Sleep Mode**

There is a function called automatic sleep mode to restrain power consumption during read-out of MBM29LV400TC/400BC data. This mode can be used effectively with an application requested low power consumption such as handy terminals.

To activate this mode, MBM29LV400TC/400BC automatically switch themselves to low power mode when MBM29LV400TC/400BC addresses remain stably during access fine of 150 ns. It is not necessary to control  $\overline{\text{CE}}$ ,  $\overline{\text{WE}}$ , and  $\overline{\text{OE}}$  on the mode. Under the mode, the current consumed is typically 1  $\mu$ A (CMOS Level).

Since the data are latched during this mode, the data are read-out continuously. If the addresses are changed, the mode is canceled automatically and MBM29LV400TC/400BC read-out the data for changed addresses.

#### **Output Disable**

With the  $\overline{OE}$  input at a logic high level ( $V_{IH}$ ), output from the devices are disabled. This will cause the output pins to be in a high impedance state.

#### Autoselect

The autoselect mode allows the reading out of a binary code from the devices and will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the devices to be programmed with its corresponding programming algorithm. This mode is functional over the entire temperature range of the devices.

To activate this mode, the programming equipment must force  $V_{ID}$  (11.5 V to 12.5 V) on address pin  $A_9$ . Two identifier bytes may then be sequenced from the devices outputs by toggling address  $A_0$  from  $V_{IL}$  to  $V_{IH}$ . All addresses are DON'T CARES except  $A_0$ ,  $A_1$ ,  $A_6$ , and  $A_{-1}$ . (See Table 4.1.)

The manufacturer and device codes may also be read via the command register, for instances when the MBM29LV400TC/BC are erased or programmed in a system without access to high voltage on the A<sub>9</sub> pin. The command sequence is illustrated in Table 7. (Refer to Autoselect Command section.)

Byte 0 ( $A_0 = V_{IL}$ ) represents the manufacturer's code (Fujitsu = 04H) and ( $A_0 = V_{IH}$ ) represents the device identifier code (MBM29LV400TC = B9H and MBM29LV400BC = BAH for  $\times 8$  mode; MBM29LV400TC = 22B9H and MBM29LV400BC = 22BAH for  $\times 16$  mode). These two bytes/words are given in the tables 4.1 and 4.2. All identifiers for manufactures and device will exhibit odd parity with DQ<sub>7</sub> defined as the parity bit. In order to read the proper device codes when executing the autoselect,  $A_1$  must be  $V_{IL}$ . (See Tables 4.1 and 4.2.)

Table 4 .1 MBM29LV400TC/400BC Sector Protection Verify Autoselect Codes

	Туре		A <sub>12</sub> to A <sub>17</sub>	<b>A</b> 6	<b>A</b> 1	Ao	<b>A</b> -1*1	Code (HEX)
Manufacture's	Code		Х	VIL	VIL	VIL	VIL	04H
	MBM29LV400TC		Х	VIL	VIL	Vih	VIL	В9Н
Device Code	MBM29LV4001C	Word	^	VIL	VIL	VIH	Х	22B9H
Device Code	MDMAQQLV/4QQDC	Byte	Х	VIL	VIL	VIH	VıL	BAH
	MBM29LV400BC		^	VIL	VIL	VIH	Х	22BAH
Sector Protecti	ion		Sector Addresses	VIL	Vıн	VIL	VIL	01H*2

<sup>\*1:</sup> A-1 is for Byte mode.

Table 4 .2 Expanded Autoselect Code Table

	Туре		Code	<b>DQ</b> <sub>15</sub>	DQ <sub>14</sub>	<b>DQ</b> <sub>13</sub>	<b>DQ</b> <sub>12</sub>	DQ <sub>11</sub>	<b>DQ</b> <sub>10</sub>	DQ <sub>9</sub>	DQ8	DQ <sub>7</sub>	DQ <sub>6</sub>	DQ₅	DQ <sub>4</sub>	DQ <sub>3</sub>	DQ <sub>2</sub>	DQ <sub>1</sub>	DQ₀
Manufacturer's Code			04H	A-1/0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0
	MBM29LV400TC	(B)	В9Н	<b>A</b> -1	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	1	0	1	1	1	0	0	1
Device	WBW29LV4001C	(W)	22B9H	0	0	1	0	0	0	1	0	1	0	1	1	1	0	0	1
Code	Code (		BAH	A-1	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	HI-Z	1	0	1	1	1	0	1	0
MBM29LV400BC (W)		22BAH	0	0	1	0	0	0	1	0	1	0	1	1	1	0	1	0	
Sector Protection			01H	A-1/0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1

(B): Byte mode(W): Word mode

<sup>\*2:</sup> Outputs 01H at protected sector addresses and outputs 00H at unprotected sector addresses.

#### Write

Device erasure and programming are accomplished via the command register. The contents of the register serve as inputs to the internal state machine. The state machine outputs dictate the function of the device.

The command register itself does not occupy any addressable memory location. The register is a latch used to store the commands, along with the address and data information needed to execute the command. The command register is written by bringing  $\overline{WE}$  to  $V_{IL}$ , while  $\overline{CE}$  is at  $V_{IL}$  and  $\overline{OE}$  is at  $V_{IH}$ . Addresses are latched on the falling edge of  $\overline{WE}$  or  $\overline{CE}$ , whichever happens later; while data is latched on the rising edge of  $\overline{WE}$  or  $\overline{CE}$ , whichever happens first. Standard microprocessor write timings are used.

Refer to AC Write Characteristics and the Erase/Programming Waveforms for specific timing parameters.

#### **Sector Protection**

The MBM29LV400TC/BC feature hardware sector protection. This feature will disable both program and erase operations in any number of sectors (0 through 10). The sector protection feature is enabled using programming equipment at the user's site. The devices are shipped with all sectors unprotected. Alternatively, Fujitsu may program and protect sectors in the factory prior to shiping the device.

To activate this mode, the programming equipment must force  $V_{ID}$  on address pin  $A_9$  and control pin  $\overline{OE}$ , (suggest  $V_{ID} = 11.5 \text{ V}$ ),  $\overline{CE} = V_{IL}$ , and  $A_6 = V_{IL}$ . The sector addresses (  $A_{17}$ ,  $A_{16}$ ,  $A_{15}$ ,  $A_{14}$ ,  $A_{13}$ , and  $A_{12}$ ) should be set to the sector to be protected. Tables 5 and 6 define the sector address for each of the eleven (11) individual sectors. Programming of the protection circuitry begins on the falling edge of the  $\overline{WE}$  pulse and is terminated with the rising edge of the same. Sector addresses must be held constant during the  $\overline{WE}$  pulse. See Figures 16 and 24 for sector protection waveforms and algorithm.

To verify programming of the protection circuitry, the programming equipment must force  $V_{ID}$  on address pin  $A_9$  with  $\overline{CE}$  and  $\overline{OE}$  at  $V_{IL}$  and  $\overline{WE}$  at  $V_{IH}$ . Scanning the sector addresses (  $A_{17}$ ,  $A_{16}$ ,  $A_{15}$ ,  $A_{14}$ ,  $A_{13}$ , and  $A_{12}$ ) while ( $A_6$ ,  $A_1$ ,  $A_0$ ) = (0, 1, 0) will produce a logical "1" code at device output DQ $_0$  for a protected sector. Otherwise the devices will read 00H for unprotected sector. In this mode, the lower order addresses, except for  $A_0$ ,  $A_1$ , and  $A_6$  are DON'T CARES. Address locations with  $A_1 = V_{IL}$  are reserved for Autoselect manufacturer and device codes.  $A_{-1}$  requires to apply to  $V_{IL}$  on byte mode.

It is also possible to determine if a sector is protected in the system by writing an Autoselect command. Performing a read operation at the address location XX02H, where the higher order addresses ( $A_{17}$ ,  $A_{16}$ ,  $A_{15}$ ,  $A_{14}$ ,  $A_{13}$ , and  $A_{12}$ ) are the desired sector address will produce a logical "1" at DQ $_0$  for a protected sector. See Tables 4.1 and 4.2 for Autoselect codes.

#### **Temporary Sector Unprotection**

This feature allows temporary unprotection of previously protected sectors of the MBM29LV400TC/BC devices in order to change data. The Sector Unprotection mode is activated by setting the RESET pin to high voltage (12 V). During this mode, formerly protected sectors can be programmed or erased by selecting the sector addresses. Once the 12 V is taken away from the RESET pin, all the previously protected sectors will be protected again. See Figures 17 and 25.

#### **RESET**

#### Hardware Reset

The MBM29LV400TC/BC devices may be reset by driving the  $\overline{RESET}$  pin to  $V_{IL}$ . The  $\overline{RESET}$  pin has a pulse requirement and has to be kept low ( $V_{IL}$ ) for at least 500 ns in order to properly reset the internal state machine. Any operation in the process of being executed will be terminated and the internal state machine will be reset to the read mode 20  $\mu$ s after the  $\overline{RESET}$  pin is driven low. Furthermore, once the  $\overline{RESET}$  pin goes high, the devices require an additional  $t_{RH}$  before it will allow read access. When the  $\overline{RESET}$  pin is low, the devices will be in the standby mode for the duration of the pulse and all the data output pins will be tri-stated. If a hardware reset occurs during a program or erase operation, the data at that particular location will be corrupted. Please note that the  $\overline{RESET}$  output signal should be ignored during the  $\overline{RESET}$  pulse. See Figure 12 for the timing diagram. Refer to Temporary Sector Unprotection for additional functionality.

If hardware reset occurs during Embedded Erase Algorithm, there is a possibility that the erasing sector(s) cannot be used.

Table 5 Sector Address Tables (MBM29LV400TC)

Sector Address	<b>A</b> 17	<b>A</b> 16	<b>A</b> 15	<b>A</b> 14	<b>A</b> 13	<b>A</b> 12	Address Range (×8)	Address Range (×16)
SA0	0	0	0	Х	Х	Х	00000H to 0FFFFH	00000H to 07FFFH
SA1	0	0	1	Х	Х	Х	10000H to 1FFFFH	08000H to 0FFFFH
SA2	0	1	0	Х	Х	Х	20000H to 2FFFFH	10000H to 17FFFH
SA3	0	1	1	Х	Х	Х	30000H to 3FFFFH	18000H to 1FFFFH
SA4	1	0	0	Х	Х	Х	40000H to 4FFFFH	20000H to 27FFFH
SA5	1	0	1	Х	Х	Х	50000H to 5FFFFH	28000H to 2FFFFH
SA6	1	1	0	Х	Х	Х	60000H to 6FFFFH	30000H to 37FFFH
SA7	1	1	1	0	Х	Х	70000H to 77FFFH	38000H to 3BFFFH
SA8	1	1	1	1	0	0	78000H to 79FFFH	3C000H to 3CFFFH
SA9	1	1	1	1	0	1	7A000H to 7BFFFH	3D000H to 3DFFFH
SA10	1	1	1	1	1	Х	7C000H to 7FFFFH	3E000H to 3FFFFH

Table 6 Sector Address Tables (MBM29LV400BC)

Sector Address	<b>A</b> 17	<b>A</b> 16	<b>A</b> 15	<b>A</b> 14	<b>A</b> 13	<b>A</b> 12	Address Range (×8)	Address Range (×16)
SA0	0	0	0	0	0	Х	00000H to 03FFFH	00000H to 01FFFH
SA1	0	0	0	0	1	0	04000H to 05FFFH	02000H to 02FFFH
SA2	0	0	0	0	1	1	06000H to 07FFFH	03000H to 03FFFH
SA3	0	0	0	1	Х	Х	08000H to 0FFFFH	04000H to 07FFFH
SA4	0	0	1	Х	Х	Х	10000H to 1FFFFH	08000H to 0FFFFH
SA5	0	1	0	Х	Х	Х	20000H to 2FFFFH	10000H to 17FFFH
SA6	0	1	1	Х	Х	Х	30000H to 3FFFFH	18000H to 1FFFFH
SA7	1	0	0	Х	Х	Х	40000H to 4FFFFH	20000H to 27FFFH
SA8	1	0	1	Х	Х	Х	50000H to 5FFFFH	28000H to 2FFFFH
SA9	1	1	0	Х	Х	Х	60000H to 6FFFFH	30000H to 37FFFH
SA10	1	1	1	Χ	Х	Χ	70000H to 7FFFFH	38000H to 3FFFFH

Table 7 MBM29LV400TC/400BC Standard Command Definitions

	Command Sequence		First Bus Write Cycle		Second Write (		Third Bus Write Cycle		Fourth Bus Read/Write Cycle		Fifth Bus Write Cycle		Sixth Bus Write Cycle	
-		Req'd	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data	Addr.	Data
Read/Reset	Word	1	XXXH	F0H										
Read/Reset	Byte	'	^^^1	FULL	_		_		_	_	_			
Dand/Danat	Word	3	555H	A A LI	2AAH	EELI	555H	F0H	DΛ	DD				
Read/Reset	Byte	3	AAAH	AAH	555H	55H	AAAH	гип	RA	RD	_	_	_	
Autoslost	Word	3	555H	A A I I	2AAH	c c l l	555H	0011						
Autoselect	Byte	3	AAAH	AAH	555H	55H	AAAH	90H	_		_	_	_	_
	Word	4	555H		2AAH		555H	4011	Β.	DD				
Program	Byte	4	AAAH	AAH	555H	55H	AAAH	A0H	PA	PD	_	_	_	_
Ohio Fores	Word	_	555H	A A I I	2AAH	c c l l	555H	0011	555H	A A I I	2AAH	E E L L	555H	4011
Chip Erase	Byte	6	AAAH	AAH	555H	55H	AAAH	80H	AAAH	AAH	555H	55H	AAAH	10H
0	Word	_	555H	A A I I	2AAH	c c l l	555H	0011	555H	A A I I	2AAH	E E L L	(	2011
Sector Erase Byte		6	AAAH	AAH	555H	55H	AAAH	80H	AAAH	AAH	555H	55H	SA	30H
Sector Eras	e Sus	pend	Erase o	an be	suspend	ded du	ring sec	tor era	se with	Addr. (	"H" or "L	"). Dat	a (B0H)	ı
Sector Erase Resume Erase can be resumed after suspend with Addr. ("H" or "L"). Data (30H)								d with	Addr. ("H	H" or "L	."). Data	(30H)		

**Notes:** 1. Address bits  $A_{11}$  to  $A_{17} = X =$  "H" or "L" for all address commands except or Program Address (PA) and Sector Address (SA)

- 2. Bus operations are defined in Tables 2 and 3.
- 3. RA = Address of the memory location to be read
  - PA = Address of the memory location to be programmed Addresses are latched on the falling edge of the  $\overline{\text{WE}}$  pulse.
  - SA = Address of the sector to be erased. The combination of A<sub>17</sub>, A<sub>16</sub>, A<sub>15</sub>, A<sub>14</sub>, A<sub>13</sub>, and A<sub>12</sub> will uniquely select any sector.
- 4. RD = Data read from location RA during read operation.
  - PD = Data to be programmed at location PA. Data is latched on the falling edge of  $\overline{WE}$ .
- 5. The system should generate the following address patterns:
  - Word Mode: 555H or 2AAH to addresses Ao to A10
  - Byte Mode: AAAH or 555H to addresses A-1 and A<sub>0</sub> to A<sub>10</sub>
- 6. Both Read/Reset commands are functionally equivalent, resetting the device to the read mode.

Table 8 MBM29LV400TC/BC Extended Command Definitions

	Command Sequence	Bus Write Cycles	First Write		Secon Write	nd Bus Cycle	Third Write	l Bus Cycle	Fourth Bus Read Cycle		
Sequenc	E	Req'd	Addr	Data	Addr	Data	Addr	Data	Addr	Data	
Set to	Word	3	555H	AAH	2AAH	55H	555H	20H			
Fast Mode	Byte	3	AAAH	AAH	555H	5511	AAAH	2011	_	_	
Fast Program	Word	2	XXXH	A0H	PA	PD					
*1	Byte	2	XXXH	Auri	FA	FD	_	_	_	_	
Reset from	Word	2	XXXH	90H	XXXH	F0H *3					
Fast Mode *1	Byte		XXXH	3011	XXXH	1011 3					
Extended	Word	4	V/V// I	60H	OD 4	0011	004	4011	004	0.0	
Sector Protect *2	Byte	4	XXXH		SPA	60H	SPA	40H	SPA	SD	

SPA: Sector address to be protected. Set sector address (SA) and  $(A_6, A_1, A_0) = (0, 1, 0)$ .

SD: Sector protection verify data. Output 01H at protected sector addresses and output 00H at unprotected sector addresses.

- \*1 This command is valid while Fast Mode.
- \*2 This command is valid while RESET = V<sub>H</sub>.
- \*3 This data "OOH" is also acceptable.

#### **Command Definitions**

Device operations are selected by writing specific address and data sequences into the command register. Writing incorrect address and data values or writing them in the improper sequence will reset the devices to the read mode. Table 7 defines the valid register command sequences. Note that the Erase Suspend (B0H) and Erase Resume (30H) commands are valid only while the Sector Erase operation is in progress. Moreover both Read/Reset commands are functionally equivalent, resetting the device to the read mode. Please note that commands are always written at  $DQ_0$  to  $DQ_7$  and  $DQ_8$  to  $DQ_{15}$  bits are ignored.

#### Read/Reset Command

In order to return from Autoselect mode or Exceeded Timing Limits (DQ5 = 1) to read/reset mode, the read/reset operation is initiated by writing the Read/Reset command sequence into the command register. Microprocessor read cycles retrieve array data from the memory. The devices remain enabled for reads until the command register contents are altered.

The devices will automatically power-up in the read/reset state. In this case, a command sequence is not required to read data. Standard microprocessor read cycles will retrieve array data. This default value ensures that no spurious alteration of the memory content occurs during the power transition. Refer to the AC Read Characteristics and Waveforms for the specific timing parameters.

#### **Autoselect Command**

Flash memories are intended for use in applications where the local CPU alters memory contents. As such, manufacture and device codes must be accessible while the devices reside in the target system. PROM programmers typically access the signature codes by raising A<sub>9</sub> to a high voltage. However, multiplexing high voltage onto the address lines is not generally desired system design practice.

The device contains an Autoselect command operation to supplement traditional PROM programming methodology. The operation is initiated by writing the Autoselect command sequence into the command register. Following the command write, a read cycle from address XX00H retrieves the manufacture code of 04H. A read cycle from address XX01H for  $\times$ 16(XX02H for  $\times$ 8) returns the device code (MBM29LV400TC = B9H and MBM29LV400BC = BAH for  $\times$ 8 mode; MBM29LV400TC = 22B9H and MBM29LV400BC = 22BAH for  $\times$ 16 mode). (See Tables 4.1 and 4.2.) All manufacturer and device codes will exhibit odd parity with DQ7 defined as the parity bit. Sector state (protection or unprotection) will be informed by address XX02H for  $\times$ 16 (XX04H for  $\times$ 8). Scanning the sector addresses (A17, A16, A15, A14, A13, and A12) while (A6, A1, A0) = (0, 1, 0) will produce a logical "1" at device output DQ0 for a protected sector. The programming verification should be perform margin mode on the protected sector. (See Tables 2 and 3.)

To terminate the operation, it is necessary to write the Read/Reset command sequence into the register, and also to write the Autoselect command during the operation, execute it after writing Read/Reset command sequence.

#### **Byte/Word Programming**

The devices are programmed on a byte-by-byte (or word-by-word) basis. Programming is a four bus cycle operation. There are two "unlock" write cycles. These are followed by the program set-up command and data write cycles. Addresses are latched on the falling edge of  $\overline{CE}$  or  $\overline{WE}$ , whichever happens later and the data is latched on the rising edge of  $\overline{CE}$  or  $\overline{WE}$ , whichever happens first. The rising edge of  $\overline{CE}$  or  $\overline{WE}$  (whichever happens first) begins programming. Upon executing the Embedded Program Algorithm command sequence, the system is not required to provide further controls or timings. The device will automatically provide adequate internally generated program pulses and verify the programmed cell margin.

The automatic programming operation is completed when the data on  $DQ_7$  is equivalent to data written to this bit at which time the devices return to the read mode and addresses are no longer latched. (See Table 9, Hardware Sequence Flags.) Therefore, the devices require that a valid address to the devices be supplied by the system at this particular instance of time. Hence,  $\overline{Data}$  Polling must be performed at the memory location which is being programmed.

Any commands written to the chip during this period will be ignored. If hardware reset occurs during the programming operation, it is impossible to guarantee the data are being written.

Programming is allowed in any sequence and across sector boundaries. Beware that a data "0" cannot be programmed back to a "1". Attempting to do so may either hang up the device or result in an apparent success according to the data polling algorithm but a read from read/reset mode will show that the data is still "0". Only erase operations can convert "0"s to "1"s.

Figure 20 illustrates the Embedded Program™ Algorithm using typical command strings and bus operations.

#### **Chip Erase**

Chip erase is a six bus cycle operation. There are two "unlock" write cycles. These are followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the chip erase command.

Chip erase does not require the user to program the device prior to erase. Upon executing the Embedded Erase Algorithm command sequence the devices will automatically program and verify the entire memory for an all zero data pattern prior to electrical erase (Preprogram function). The system is not required to provide any controls or timings during these operations.

The automatic erase begins on the rising edge of the last  $\overline{\text{WE}}$  pulse in the command sequence and terminates when the data on DQ<sub>7</sub> is "1" (See Write Operation Status section.) at which time the device returns to read the mode.

Chip Erase Time; Sector Erase Time × All sectors + Chip Program Time (Preprogramming)

Figure 21 illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

#### Sector Erase

Sector erase is a six bus cycle operation. There are two "unlock" write cycles. These are followed by writing the "set-up" command. Two more "unlock" write cycles are then followed by the Sector Erase command. The sector address (any address location within the desired sector) is latched on the falling edge of  $\overline{\text{WE}}$ , while the command (Data=30H) is latched on the rising edge of  $\overline{\text{WE}}$ . After time-out of 50  $\mu$ s from the rising edge of the last sector erase command, the sector erase operation will begin.

Multiple sectors may be erased concurrently by writing the six bus cycle operations on Table 7. This sequence is followed with writes of the Sector Erase command to addresses in other sectors desired to be concurrently erased. The time between writes must be less than 50  $\mu$ s otherwise that command will not be accepted and erasure will start. It is recommended that processor interrupts be disabled during this time to guarantee this condition. The interrupts can be re-enabled after the last Sector Erase command is written. A time-out of 50  $\mu$ s from the rising edge of the last  $\overline{WE}$  will initiate the execution of the Sector Erase command(s). If another falling edge of the  $\overline{WE}$  occurs within the 50  $\mu$ s time-out window the timer is reset. (Monitor DQ3 to determine if the sector erase timer window is still open, see section DQ3, Sector Erase Timer.) Any command other than Sector Erase or Erase Suspend during this time-out period will reset the devices to the read mode, ignoring the previous command string. Resetting the devices once execution has begun will corrupt the data in the sector. In that case, restart the erase on those sectors and allow them to complete. (Refer to the Write Operation Status section for Sector Erase Timer operation.) Loading the sector erase buffer may be done in any sequence and with any number of sectors (0 to 10).

Sector erase does not require the user to program the devices prior to erase. The devices automatically program all memory locations in the sector(s) to be erased prior to electrical erase (Preprogram function). When erasing a sector or sectors the remaining unselected sectors are not affected. The system is not required to provide any controls or timings during these operations.

The automatic sector erase begins after the 50  $\mu$ s time out from the rising edge of the WE pulse for the last sector erase command pulse and terminates when the data on DQ<sub>7</sub> is "1" (See Write Operation Status section.) at which time the devices return to the read mode. Data polling must be performed at an address within any of the sectors being erased. Multiple Sector Erase Time; [Sector Erase Time + Sector Program Time (Preprogramming)]  $\times$  Number of Sector Erase

Figure 21 illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

#### **Erase Suspend**

The Erase Suspend command allows the user to interrupt a Sector Erase operation and then perform data reads from or programs to a sector not being erased. This command is applicable ONLY during the Sector Erase operation which includes the time-out period for sector erase. The Erase Suspend command will be ignored if written during the Chip Erase operation or Embedded Program Algorithm. Writting the Erase Suspend command during the Sector Erase time-out results in immediate termination of the time-out period and suspension of the erase operation.

Writing the Erase Resume command resumes the erase operation. The addresses are DON'T CARES when writing the Erase Suspend or Erase Resume command.

When the Erase Suspend command is written during the Sector Erase operation, the device will take a maximum of 20  $\mu$ s to suspend the erase operation. When the devices have entered the erase-suspended mode, the RY/  $\overline{BY}$  output pin and the DQ<sub>7</sub> bit will be at logic "1", and DQ<sub>6</sub> will stop toggling. The user must use the address of the erasing sector for reading DQ<sub>6</sub> and DQ<sub>7</sub> to determine if the erase operation has been suspended. Further writes of the Erase Suspend command are ignored.

When the erase operation has been suspended, the devices default to the erase-suspend-read mode. Reading data in this mode is the same as reading from the standard read mode except that the data must be read from sectors that have not been erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-read mode will cause DQ<sub>2</sub> to toggle. (See the section on DQ<sub>2</sub>.)

After entering the erase-suspend-read mode, the user can program the device by writing the appropriate command sequence for Program. This program mode is known as the erase-suspend-program mode. Again, programming in this mode is the same as programming in the regular Program mode except that the data must be programmed to sectors that are not erase-suspended. Successively reading from the erase-suspended sector while the devices are in the erase-suspend-program mode will cause  $DQ_2$  to toggle. The end of the erase-suspended Program operation is detected by the RY/ $\overline{BY}$  output pin,  $\overline{Data}$  polling of  $DQ_7$ , or by the Toggle Bit I ( $DQ_6$ ) which is the same as the regular Program operation. Note that  $DQ_7$  must be read from the Program address while  $DQ_6$  can be read from any address.

To resume the operation of Sector Erase, the Resume command (30H) should be written. Any further writes of the Resume command at this point will be ignored. Another Erase Suspend command can be written after the chip has resumed erasing.

#### **Extended Command**

#### (1) Fast Mode

MBM29LV400TC/BC has Fast Mode function. This mode dispenses with the initial two unclock cycles required in the standard program command sequence by writing Fast Mode command into the command register. In this mode, the required bus cycle for programming is two cycles instead of four bus cycles in standard program command. (Do not write erase command in this mode.) The read operation is also executed after exiting this mode. To exit this mode, it is necessary to write Fast Mode Reset command into the command register. (Refer to the Figure 27 Extended algorithm.) The  $V_{CC}$  active current is required even  $\overline{CE} = V_{IH}$  during Fast Mode.

#### (2) Fast Programming

During Fast Mode, the programming can be executed with two bus cycles operation. The Embedded Program Algorithm is executed by writing program set-up command (A0H) and data write cycles (PA/PD). (Refer to the Figure 27 Extended algorithm.)

#### (3) Extended Sector Protection

In addition to normal sector protection, the MBM29LV400TC/BC has Extended Sector Protection as extended function. This function enable to protect sector by forcing  $V_{ID}$  on  $\overline{RESET}$  pin and write a commnad sequence. Unlike conventional procedure, it is not necessary to force  $V_{ID}$  and control timing for control pins. The only  $\overline{RESET}$  pin requires  $V_{ID}$  for sector protection in this mode. The extended sector protect requires  $V_{ID}$  on  $\overline{RESET}$  pin. With this condition, the operation is initiated by writing the set-up command (60H) into the command register. Then, the sector addresses pins (A<sub>17</sub>, A<sub>16</sub>, A<sub>15</sub>, A<sub>14</sub>, A<sub>13</sub> and A<sub>12</sub>) and (A<sub>6</sub>, A<sub>1</sub>, A<sub>0</sub>) = (0, 1, 0) should be set to the sector to be protected (recommend to set  $V_{IL}$  for the other addresses pins), and write extended sector protect command (60H). A sector is typically protected in 150  $\mu$ s. To verify programming of the protection circuitry, the sector addresses pins (A<sub>17</sub>, A<sub>16</sub>, A<sub>15</sub>, A<sub>14</sub>, A<sub>13</sub> and A<sub>12</sub>) and (A<sub>6</sub>, A<sub>1</sub>, A<sub>0</sub>) = (0, 1, 0) should be set and write a command (40H). Following the command write, a logical "1" at device output DQ<sub>0</sub> will produce for protected sector in the read operation. If the output data is logical "0", please repeat to write extended sector protect command (60H) again. To terminate the operation, it is necessary to set  $\overline{RESET}$  pin to  $V_{IH}$ .

#### **Write Operation Status**

**Table 9 Hardware Sequence Flags** 

		Status	DQ <sub>7</sub>	$DQ_6$	DQ <sub>5</sub>	DQ <sub>3</sub>	$DQ_2$
	Embedded F	Program Algorithm	DQ <sub>7</sub>	Toggle	0	0	1
	Embedded E	rase Algorithm	0	Toggle	0	1	Toggle
In Progress	Erase Suspended Mode	Erase Suspend Read (Erase Suspended Sector)	1	1	0	0	Toggle
and regions		Erase Suspend Read (Non-Erase Suspended Sector)	Data	Data	Data	Data	Data
		Erase Suspend Program (Non-Erase Suspended Sector)	DQ <sub>7</sub>	Toggle (Note 1)	0	0	1 (Note 2)
	Embedded F	Program Algorithm	DQ <sub>7</sub>	Toggle	1	0	1
Exceeded Time Limits	Embedded E	rase Algorithm	0	Toggle	1	1	N/A
	Erase Suspended Mode	Erase Suspend Program (Non-Erase Suspended Sector)	DQ <sub>7</sub>	Toggle	1	0	N/A

Notes: 1. Performing successive read operations from any address will cause DQ₀ to toggle.

- 2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ<sub>2</sub> bit. However, successive reads from the erase-suspended sector will cause DQ<sub>2</sub> to toggle.
- 3.  $DQ_0$  and  $DQ_1$  are reserve pins for future use.
- 4. DQ4 is Fujitsu internal use only.

#### DQ<sub>7</sub>

#### Data Polling

The MBM29LV400TC/BC devices feature  $\overline{Data}$  Polling as a method to indicate to the host that the Embedded Algorithms are in progress or completed. During the Embedded Program Algorithm an attempt to read the devices will produce the complement of the data last written to  $DQ_7$ . Upon completion of the Embedded Program Algorithm, an attempt to read the device will produce the true data last written to  $DQ_7$ . During the Embedded Erase Algorithm, an attempt to read the device will produce a "0" at the  $DQ_7$  output. Upon completion of the Embedded Erase Algorithm an attempt to read the device will produce a "1" at the  $DQ_7$  output. The flowchart for  $\overline{Data}$  Polling ( $DQ_7$ ) is shown in Figure 22.

For chip erase and sector erase, the  $\overline{Data}$  Polling is valid after the rising edge of the sixth  $\overline{WE}$  pulse in the six write pulse sequence.  $\overline{Data}$  Polling must be performed at sector address within any of the sectors being erased and not a protected sector. Otherwise, the status may not be valid. Once the Embedded Algorithm operation is close to being completed, the MBM29LV400TC/BC data pins ( $\overline{DQ_7}$ ) may change asynchronously while the output enable ( $\overline{OE}$ ) is asserted low. This means that the devices are driving status information on  $\overline{DQ_7}$  at one instant of time and then that byte's valid data at the next instant of time. Depending on when the system samples the  $\overline{DQ_7}$  output, it may read the status or valid data. Even if the device has completed the Embedded Algorithm operation and  $\overline{DQ_7}$  has a valid data, the data outputs on  $\overline{DQ_0}$  to  $\overline{DQ_6}$  may be still invalid. The valid data on  $\overline{DQ_0}$  to  $\overline{DQ_7}$  will be read on the successive read attempts.

The Data Polling feature is only active during the Embedded Programming Algorithm, Embedded Erase Algorithm or sector erase time-out. (See Table 9.)

See Figure 9 for the Data Polling timing specifications and diagrams.

#### $DQ_6$

#### Toggle Bit I

The MBM29LV400TC/BC also feature the "Toggle Bit I" as a method to indicate to the host system that the Embedded Algorithms are in progress or completed.

During an Embedded Program or Erase Algorithm cycle, successive attempts to read ( $\overline{OE}$  toggling) data from the devices will result in DQ6 toggling between one and zero. Once the Embedded Program or Erase Algorithm cycle is completed, DQ6 will stop toggling and valid data will be read on the next successive attempts. During programming, the Toggle Bit I is valid after the rising edge of the fourth  $\overline{WE}$  pulse in the four write pulse sequence. For chip erase and sector erase, the Toggle Bit I is valid after the rising edge of the sixth  $\overline{WE}$  pulse in the six write pulse sequence. The Toggle Bit I is active during the sector time out.

In programming, if the sector being written to is protected, the toggle bit will toggle for about  $2\,\mu s$  and then stop toggling without the data having changed. In erase, the devices will erase all the selected sectors except for the ones that are protected. If all selected sectors are protected, the chip will toggle the toggle bit for about 100  $\mu s$  and then drop back into read mode, having changed none of the data.

Either  $\overline{\text{CE}}$  or  $\overline{\text{OE}}$  toggling will cause the DQ6 to toggle. In addition, an Erase Suspend/Resume command will cause the DQ6 to toggle.

See Figure 10 for the Toggle Bit I timing specifications and diagrams.

#### $DQ_5$

#### **Exceeded Timing Limits**

 $DQ_5$  will indicate if the program or erase time has exceeded the specified limits (internal pulse count). Under these conditions  $DQ_5$  will produce a "1". This is a failure condition which indicates that the program or erase cycle was not successfully completed.  $\overline{Data}$  Polling is the only operating function of the devices under this condition. The  $\overline{CE}$  circuit will partially power down the device under these conditions (to approximately 2 mA). The  $\overline{OE}$  and  $\overline{WE}$  pins will control the output disable functions as described in Tables 2 and 3.

The DQ $_5$  failure condition may also appear if a user tries to program a non blank location without erasing. In this case the devices lock out and never complete the Embedded Algorithm operation. Hence, the system never reads a valid data on DQ $_7$  bit and DQ $_6$  never stops toggling. Once the devices have exceeded timing limits, the DQ $_5$  bit will indicate a "1." Please note that this is not a device failure condition since the devices were incorrectly used. If this occurs, reset the device with command sequence.

#### DQ<sub>3</sub>

#### Sector Erase Timer

After the completion of the initial sector erase command sequence the sector erase time-out will begin. DQ<sub>3</sub> will remain low until the time-out is complete. Data Polling and Toggle Bit are valid after the initial sector erase command sequence.

If Data Polling or the Toggle Bit I indicates the device has been written with a valid erase command, DQ<sub>3</sub> may be used to determine if the sector erase timer window is still open. If DQ<sub>3</sub> is high ("1") the internally controlled erase cycle has begun; attempts to write subsequent commands to the device will be ignored until the erase operation is completed as indicated by Data Polling or Toggle Bit I. If DQ<sub>3</sub> is low ("0"), the device will accept additional sector erase commands. To insure the command has been accepted, the system software should check the status of DQ<sub>3</sub> prior to and following each subsequent Sector Erase command. If DQ<sub>3</sub> were high on the second status check, the command may not have been accepted.

See Table 9: Hardware Sequence Flags.

#### $DQ_2$

#### Toggle Bit II

This toggle bit II, along with DQ<sub>6</sub>, can be used to determine whether the devices are in the Embedded Erase Algorithm or in Erase Suspend.

Successive reads from the erasing sector will cause  $DQ_2$  to toggle during the Embedded Erase Algorithm. If the devices are in the erase-suspended-read mode, successive reads from the erase-suspended sector will cause  $DQ_2$  to toggle. When the devices are in the erase-suspended-program mode, successive reads from the byte address of the non-erase suspended sector will indicate a logic "1" at the  $DQ_2$  bit.

DQ<sub>6</sub> is different from DQ<sub>2</sub> in that DQ<sub>6</sub> toggles only when the standard program or Erase, or Erase Suspend Program operation is in progress. The behavior of these two status bits, along with that of DQ<sub>7</sub>, is summarized as follows:

For example, DQ<sub>2</sub> and DQ<sub>6</sub> can be used together to determine if the erase-suspend-read mode is in progress. (DQ<sub>2</sub> toggles while DQ<sub>6</sub> does not.) See also Table 9 and Figure 18.

Furthermore,  $DQ_2$  can also be used to determine which sector is being erased. When the device is in the erase mode,  $DQ_2$  toggles if this bit is read from an erasing sector.

Mode	DQ <sub>7</sub>	DQ <sub>6</sub>	DQ₂
Program	ŪQ₁	Toggle	1
Erase	0	Toggle	Toggle
Erase-Suspend Read (Erase-Suspended Sector) (Note 1)	1	1	Toggle
Erase-Suspend Program	ŪQ <sub>7</sub>	Toggle (Note 1)	1 (Note 2)

- Notes: 1. Performing successive read operations from any address will cause DQ6 to toggle.
  - 2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ<sub>2</sub> bit. However, successive reads from the erase-suspended sector will cause DQ<sub>2</sub> to toggle.

#### RY/BY

#### Ready/Busy

The MBM29LV400TC/BC provide a RY/BY open-drain output pin as a way to indicate to the host system that the Embedded Algorithms are either in progress or has been completed. If the output is low, the devices are busy with either a program or erase operation. If the output is high, the devices are ready to accept any read/write or erase operation. When the RY/BY pin is low, the devices will not accept any additional program or erase commands. If the MBM29LV400TC/BC are placed in an Erase Suspend mode, the RY/BY output will be high.

During programming, the RY/ $\overline{BY}$  pin is driven low after the rising edge of the fourth  $\overline{WE}$  pulse. During an erase operation, the RY/ $\overline{BY}$  pin is driven low after the rising edge of the sixth  $\overline{WE}$  pulse. The RY/ $\overline{BY}$  pin will indicate a busy condition during the  $\overline{RESET}$  pulse. Refer to Figure 11 and 12 for a detailed timing diagram. The RY/ $\overline{BY}$  pin is pulled high in standby mode.

Since this is an open-drain output, RY/BY pins can be tied together in parallel with a pull-up resistor to Vcc.

#### **Byte/Word Configuration**

The BYTE pin selects the byte (8-bit) mode or word (16-bit) mode for the MBM29LV400TC/BC devices. When this pin is driven high, the devices operate in the word (16-bit) mode. The data is read and programmed at DQ0 to DQ15. When this pin is driven low, the devices operate in byte (8-bit) mode. Under this mode, the DQ15/A-1 pin becomes the lowest address bit and DQ8 to DQ14 bits are tri-stated. However, the command bus cycle is always an 8-bit operation and hence commands are written at DQ0 to DQ7 and the DQ8 to DQ15 bits are ignored. Refer to Figures 13, 14 and 15 for the timing diagram.

#### **Data Protection**

The MBM29LV400TC/BC are designed to offer protection against accidental erasure or programming caused by spurious system level signals that may exist during power transitions. During power up the devices automatically reset the internal state machine in the Read mode. Also, with its control register architecture, alteration of the memory contents only occurs after successful completion of specific multi-bus cycle command sequences.

The devices also incorporate several features to prevent inadvertent write cycles resulting form Vcc power-up and power-down transitions or system noise.

#### Low Vcc Write Inhibit

To avoid initiation of a write cycle during  $V_{\rm CC}$  power-up and power-down, a write cycle is locked out for  $V_{\rm CC}$  less than 2.3 V (typically 2.4 V). If  $V_{\rm CC}$  <  $V_{\rm LKO}$ , the command register is disabled and all internal program/erase circuits are disabled. Under this condition the device will reset to the read mode. Subsequent writes will be ignored until the  $V_{\rm CC}$  level is greater than  $V_{\rm LKO}$ . It is the users responsibility to ensure that the control pins are logically correct to prevent unintentional writes when  $V_{\rm CC}$  is above 2.3 V.

If Embedded Erase Algorithm is interrupted, there is possibility that the erasing sector(s) cannot be used.

#### Write Pulse "Glitch" Protection

Noise pulses of less than 5 ns (typical) on  $\overline{OE}$ ,  $\overline{CE}$ , or  $\overline{WE}$  will not initiate a write cycle.

#### **Logical Inhibit**

Writing is inhibited by holding any one of  $\overline{OE} = V_{IL}$ ,  $\overline{CE} = V_{IH}$ , or  $\overline{WE} = V_{IH}$ . To initiate a write cycle  $\overline{CE}$  and  $\overline{WE}$  must be a logical zero while  $\overline{OE}$  is a logical one.

#### **Power-Up Write Inhibit**

Power-up of the devices with  $\overline{WE} = \overline{CE} = V_{\parallel}$  and  $\overline{OE} = V_{\parallel}$  will not accept commands on the rising edge of  $\overline{WE}$ . The internal state machine is automatically reset to the read mode on power-up.

#### ■ ABSOLUTE MAXIMUM RATINGS

Storage Temperature	–55°C to +125°C
Ambient Temperature with Power Applied	40°C to +85°C
Voltage with respect to Ground All pins except A <sub>9</sub> , OE, RESET (Note 1	)0.5 V to Vcc+0.5 V
Vcc (Note 1)	0.5 V to +5.5 V
A <sub>9</sub> , $\overline{OE}$ , and $\overline{RESET}$ (Note 2)	0.5 V to +13.0 V

- **Notes:** 1. Minimum DC voltage on input or I/O pins are -0.5 V. During voltage transitions, inputs may negative overshoot Vss to -2.0 V for periods of up to 20 ns. Maximum DC voltage on output and I/O pins are Vcc +0.5 V. During voltage transitions, outputs may positive overshoot to Vcc +2.0 V for periods of up to 20 ns.
  - 2. Minimum DC input voltage on A<sub>9</sub>, <del>OE</del> and <del>RESET</del> pins are −0.5 V. During voltage transitions, A9, <del>OE</del> and <del>RESET</del> pins may negative overshoot V<sub>SS</sub> to −2.0 V for periods of up to 20 ns. Maximum DC input voltage on A<sub>9</sub>, <del>OE</del> and <del>RESET</del> pins are +13.0 V which may positive overshoot to 14.0 V for periods of up to 20 ns. Voltage difference between input voltage and supply voltage (V<sub>IN</sub> − V<sub>CC</sub>) do not exceed 9 V.

**WARNING:** Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

#### ■ RECOMMENDED OPERATING RANGES

Ambient Temperature (T <sub>A</sub> )	. –40°C to +85°C
Vcc Supply Voltages	
MBM29LV400TC/BC-70	. +3.0 V to +3.6 V
MBM29LV400TC/BC-90/-12	. +2.7 V to +3.6 V

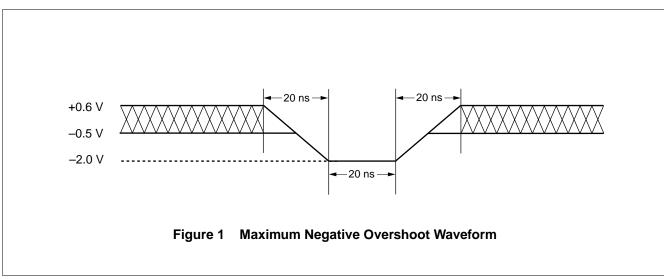
Operating ranges define those limits between which the functionality of the devices are guaranteed.

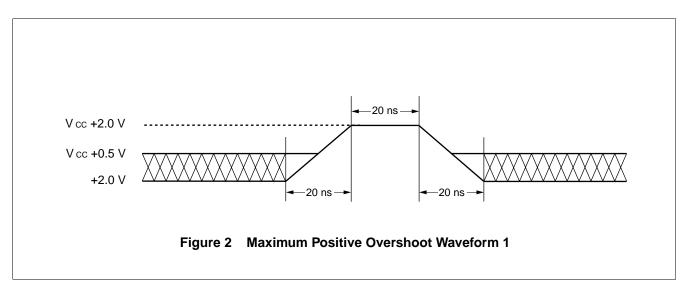
**WARNING:** The recommended operating conditions are required in to ensure the normal operation of ranges for the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

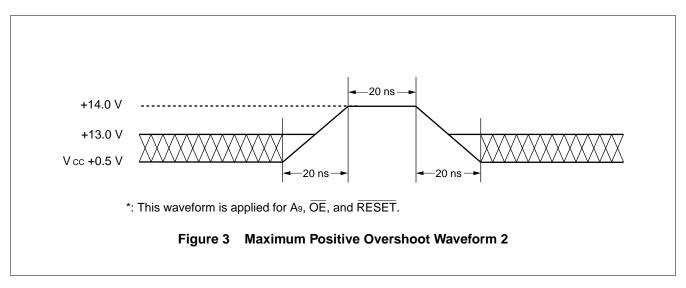
Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

#### **■ MAXIMUM OVERSHOOT**







#### **■ DC CHARACTERISTICS**

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit	
lu	Input Leakage Current	VIN = Vss to Vcc, Vcc = Vcc	-1.0	+1.0	μΑ	
<b>I</b> LO	Output Leakage Current	Vout = Vss to Vcc, Vcc = Vc	c Max.	-1.0	+1.0	μΑ
Інт	A <sub>9</sub> , <del>OE</del> , <del>RESET</del> Inputs Leakage Current	Vcc = Vcc Max. A <sub>9</sub> , OE, RESET = 12.5 V			35	μА
		$\overline{CE} = V_{IL}, \overline{OE} = V_{IH},$	Byte		22	mA
laa.	Ves Astivo Current (Note 1)	f=10 MHz	Word	_	25	IIIA
Icc1	Vcc Active Current (Note 1)	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH},$	Byte		12	A
		f=5 MHz	Word	_	15	mA
Icc2	Vcc Active Current (Note 2)	$\overline{CE} = V_{IL}, \overline{OE} = V_{IH}$		_	35	mA
Іссз	Vcc Current (Standby)	$\frac{\text{Vcc} = \text{Vcc Max., } \overline{\text{CE}} = \text{Vcc}}{\text{RESET}} = \text{Vcc} \pm 0.3 \text{ V}$	_	5	μА	
Icc4	Vcc Current (Standby, Reset)	Vcc = Vcc Max., RESET = Vss ± 0.3 V	_	5	μА	
Icc5	Vcc Current (Automatic Sleep Mode) (Note 3)		_	5	μΑ	
VIL	Input Low Level	_		-0.5	0.6	V
ViH	Input High Level	_		2.0	Vcc+0.3	V
VID	Voltage for Autoselect and Sector Protection (A <sub>9</sub> , OE, RESET) (Note 4)	_	11.5	12.5	V	
Vol	Output Low Voltage Level	IoL = 4.0 mA, Vcc = Vcc Min	_	0.45	V	
V <sub>OH1</sub>	Output High Voltage Level	Iон = −2.0 mA, Vcc = Vcc M	lin.	2.4	_	V
V <sub>OH2</sub>	Output High Voltage Level	Іон = −100 μА		Vcc-0.4	_	V
VLKO	Low Vcc Lock-Out Voltage	_		2.3	2.5	V

**Notes:** 1. The lcc current listed includes both the DC operating current and the frequency dependent component (at 10 MHz).

- 2. Icc active while Embedded Algorithm (program or erase) is in progress.
- 3. Automatic sleep mode enables the low power mode when address remain stable for 150 ns.
- 4.  $(V_{ID} V_{CC})$  do not exceed 9 V.

#### **■ AC CHARACTERISTICS**

• Read Only Operations Characteristics

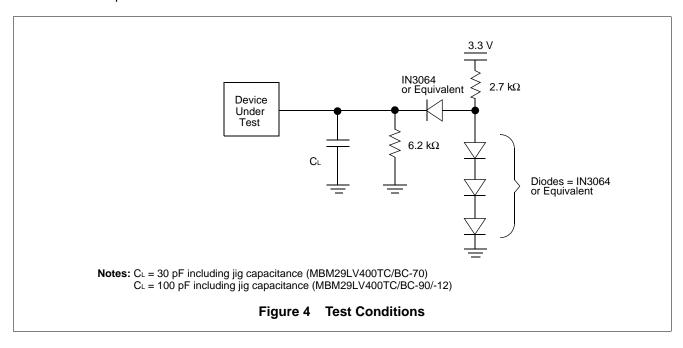
	meter nbols	Description	Test Setup		-70 (Note)	-90 (Note)	-12 (Note)	Unit
JEDEC	Standard	·		-	(NOLE)	(NOIE)	(NOTE)	
tavav	<b>t</b> RC	Read Cycle Time	_	Min.	70	90	120	ns
tavqv	tacc	Address to Output Delay	$\frac{\overline{CE}}{\overline{OE}} = V_{IL}$ Max.		70	90	120	ns
<b>t</b> ELQV	<b>t</b> ce	Chip Enable to Output Delay	Chip Enable to Output Delay $\overline{OE} = V_{IL}$ Max.		70	90	120	ns
<b>t</b> GLQV	toe	Output Enable to Output Delay	_	Max.	30	35	50	ns
<b>t</b> ehqz	<b>t</b> DF	Chip Enable to Output High-Z	_	Max.	25	30	30	ns
<b>t</b> GHQZ	<b>t</b> DF	Output Enable to Output High-Z	_	Max.	25	30	30	ns
taxqx	tон	Output Hold Time From Addresses, CE or OE, Whichever Occurs First	_	Min.	0	0	0	ns
_	<b>t</b> READY	RESET Pin Low to Read Mode	_	Max.	20	20	20	μs
_	telfl telfh	CE or BYTE Switching Low or High	_	Max.	5	5	5	ns

**Note:** Test Conditions:

Output Load: 1 TTL gate and 30 pF (MBM29LV400TC/BC-70) 1 TTL gate and 100 pF (MBM29LV400TC/BC-90/-12)

Input rise and fall times: 5 ns Input pulse levels: 0.0 V to 3.0 V Timing measurement reference level

Input: 1.5 V Output:1.5 V



#### • Write/Erase/Program Operations

Parameter Symbols			Decembelon		MBM29LV400TC/BC			11
JEDEC	Standard		Description		-70	-90	-12	- Unit
tavav	twc	Write Cycle Ti	me	Min.	70	90	120	ns
<b>t</b> avwl	tas	Address Setup	Time	Min.	0	0	0	ns
twlax	<b>t</b> AH	Address Hold	Address Hold Time		45	45	50	ns
<b>t</b> dvwh	tos	Data Setup Tir	ne	Min.	35	45	50	ns
twhdx	tон	Data Hold Tim	е	Min.	0	0	0	ns
_	toes	Output Enable	Setup Time	Min.	0	0	0	ns
		Output	Read	Min.	0	0	0	ns
_	toeh Enable Hold Time	Toggle and Data Polling	Min.	10	10	10	ns	
<b>t</b> GHWL	<b>t</b> GHWL	Read Recover	Time Before Write	Min.	0	0	0	ns
<b>t</b> GHEL	<b>t</b> GHEL	Read Recover	Time Before Write	Min.	0	0	0	ns
<b>t</b> ELWL	tcs	CE Setup Time	CE Setup Time		0	0	0	ns
twlel	tws	WE Setup Tim	e	Min.	0	0	0	ns
twheh	<b>t</b> cH	CE Hold Time	E Hold Time		0	0	0	ns
<b>t</b> EHWH	twн	WE Hold Time		Min.	0	0	0	ns
twlwh	twp	Write Pulse Width		Min.	35	45	50	ns
<b>t</b> ELEH	<b>t</b> CP	CE Pulse Width		Min.	35	45	50	ns
<b>t</b> whwL	<b>t</b> wph	Write Pulse Width High		Min.	25	25	30	ns
<b>t</b> ehel	<b>t</b> CPH	CE Pulse Width High		Min.	25	25	30	ns
<b>t</b> whwh1	twhwh1	Byte Programm	Byte Programming Operation		8	8	8	μs
<b>t</b> whwh2	<b>t</b> whwh2	Sector Erase (	Operation (Note 1)	Тур.	1	1	1	sec
_	tvcs	Vcc Setup Tim	е	Min.	50	50	50	μs
_	tvidr	Rise Time to V	/ID (Note 2)	Min.	500	500	500	ns
_	<b>t</b> vlht	Voltage Transi	tion Time (Note 2)	Min.	4	4	4	μs
_	twpp	Write Pulse W	idth (Note 2)	Min.	100	100	100	μs
_	toesp	OE Setup Tim	OE Setup Time to WE Active (Note 2)		4	4	4	μs
_	tcsp	CE Setup Time	e to WE Active (Note 2)	Min.	4	4	4	μs
_	<b>t</b> RB	Recover Time	From RY/BY	Min.	0	0	0	ns
_	<b>t</b> RP	RESET Pulse	Width	Min.	500	500	500	ns
_	<b>t</b> RH	RESET Hold 1	ime Before Read	Min.	200	200	200	ns

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#### (Continued)

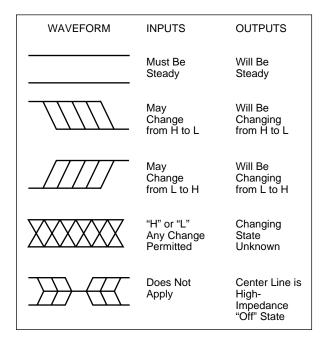
Parameter Symbols		Description		MBM2	Unit		
JEDEC	Standard	Description	-70	-90	-12	Onit	
_	<b>t</b> FLQZ	BYTE Switching Low to Output High-Z	Max.	30	35	50	ns
_	<b>t</b> FHQV	BYTE Switching High to Output Active	Min.	30	35	50	ns
_	<b>t</b> BUSY	Program/Erase Valid to RY/BY Delay	Max.	90	90	90	ns
_	<b>t</b> EOE	Delay Time from Embedded Output Enable	Max.	30	35	50	ns

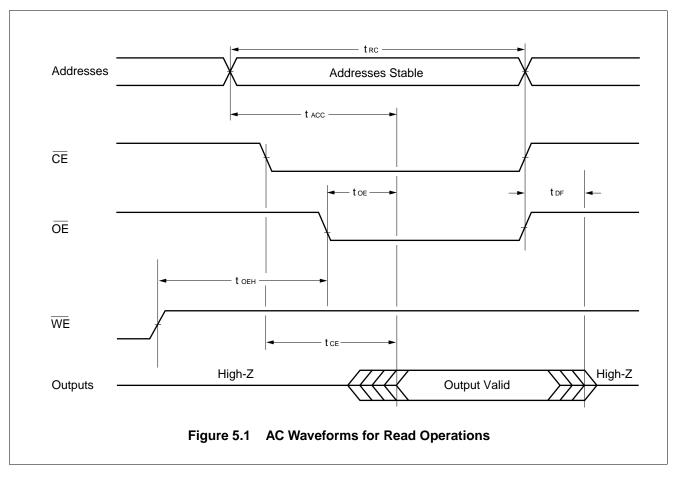
**Notes:** 1. This does not include the preprogramming time.

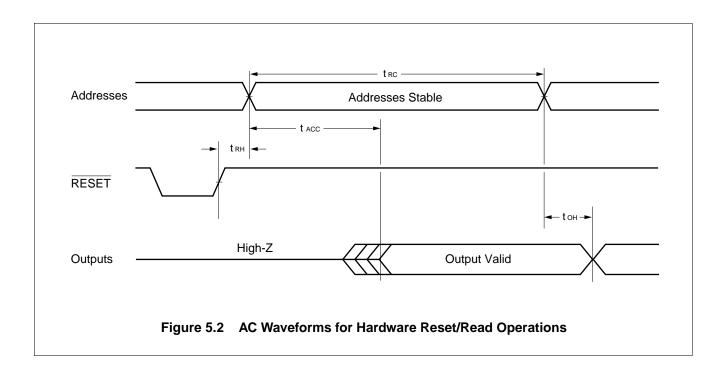
2. This timing is for Sector Protection operation.

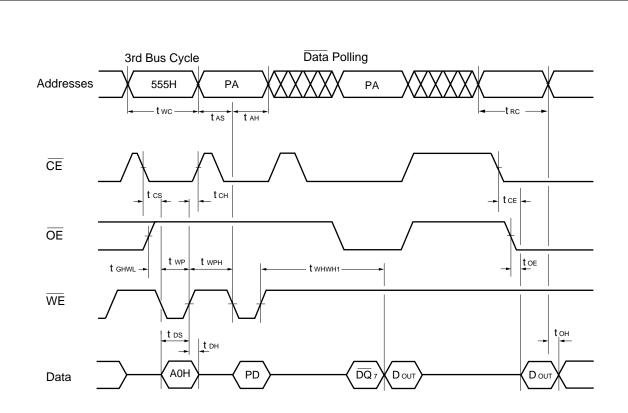
#### **■ SWITCHING WAVEFORMS**

Key to Switching Waveforms





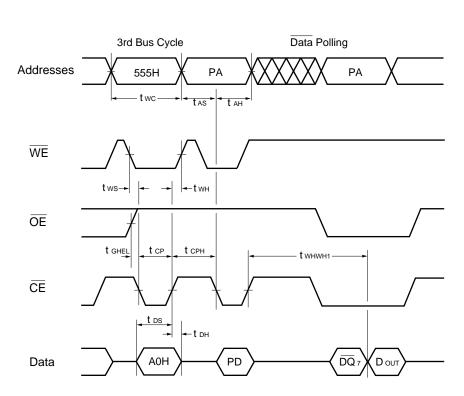




**Notes:** 1. PA is address of the memory location to be programmed.

- 2. PD is data to be programmed at byte address.
- 3.  $\overline{DQ_7}$  is the output of the complement of the data written to the device.
- 4. Dout is the output of the data written to the device.
- 5. Figure indicates last two bus cycles out of four bus cycle sequence.
- 6. These waveforms are for the ×16 mode. (The addresses differ from ×8 mode.)

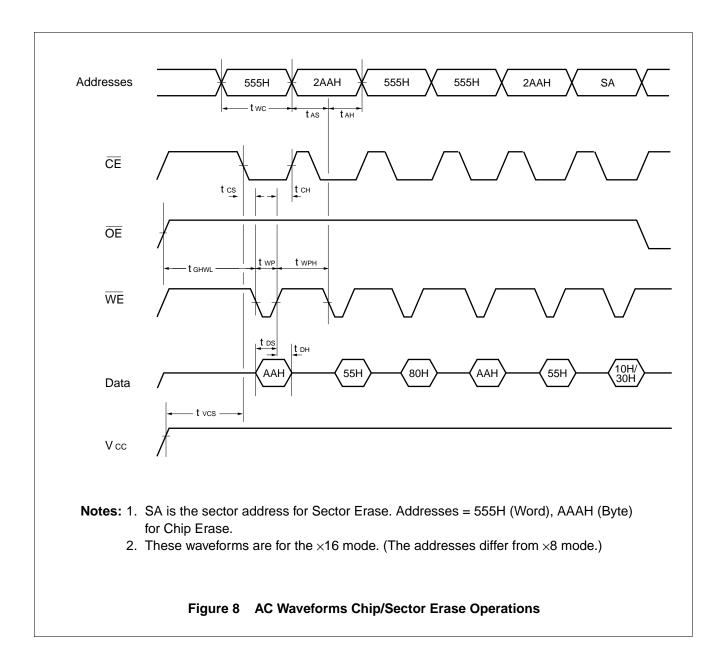
Figure 6 AC Waveforms for Alternate WE Controlled Program Operations

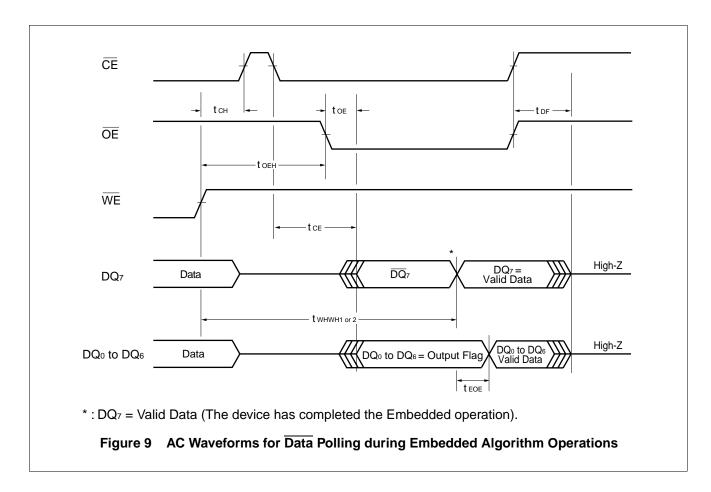


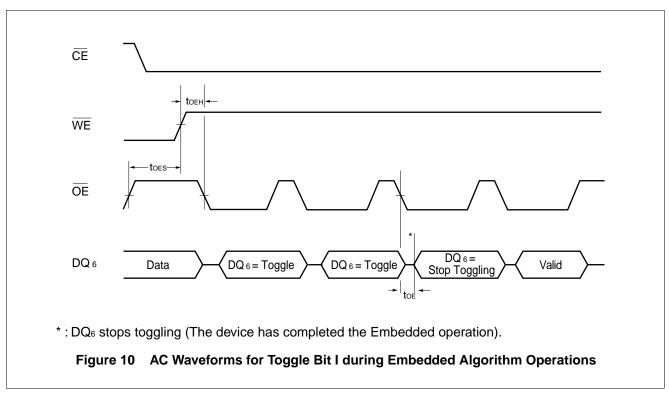
**Notes:** 1. PA is address of the memory location to be programmed.

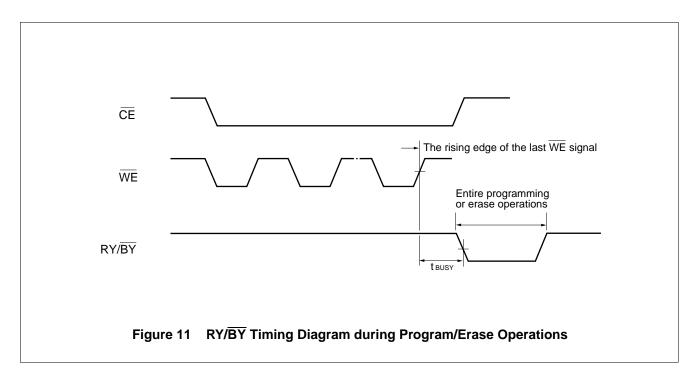
- 2. PD is data to be programmed at byte address.
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- 6. These waveforms are for the ×16 mode. (The addresses differ from ×8 mode.)

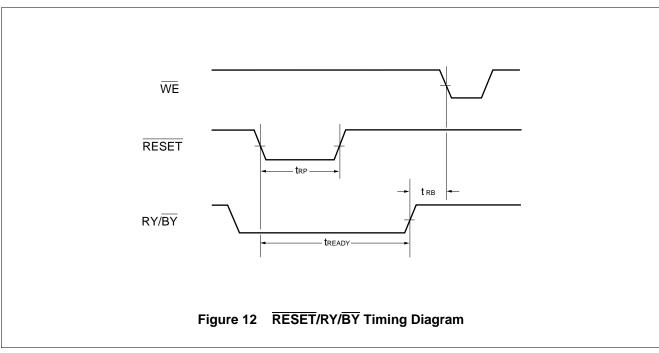
Figure 7 AC Waveforms for Alternate CE Controlled Program Operations

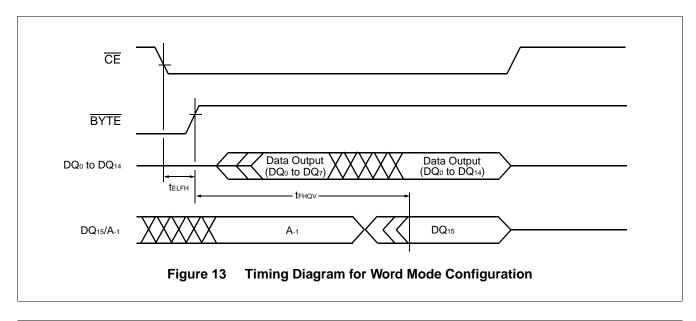


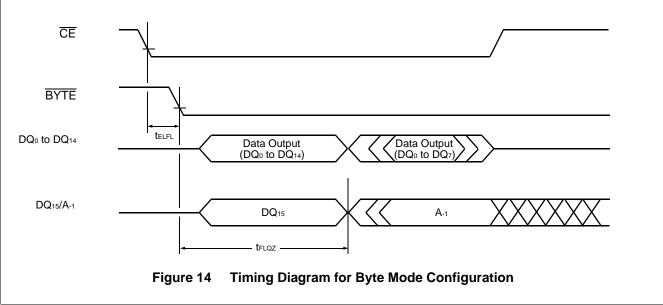


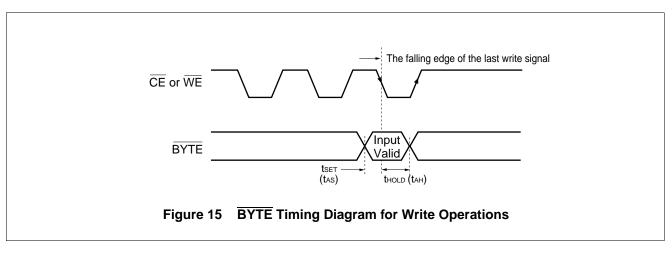


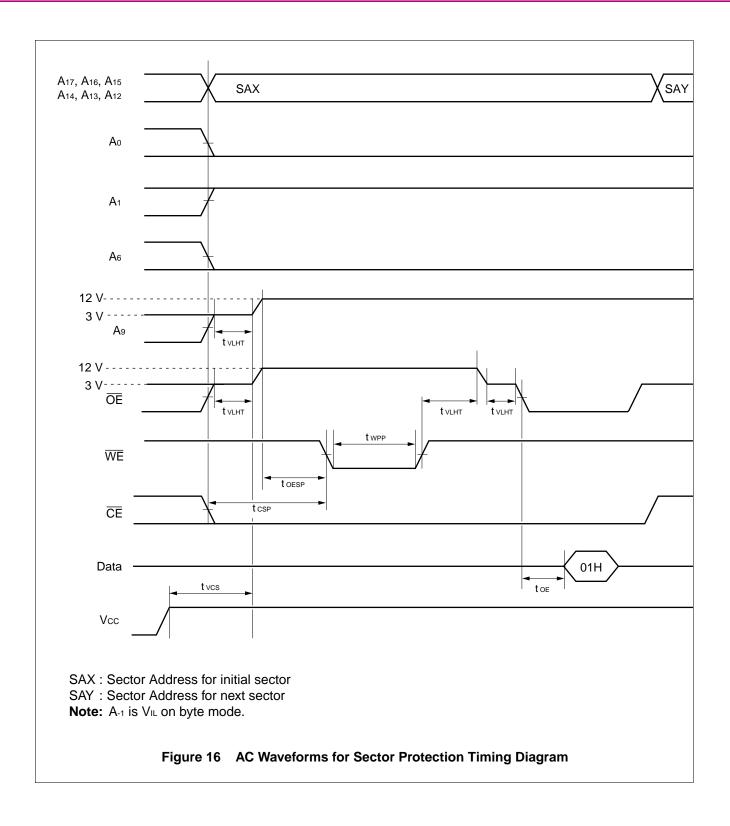


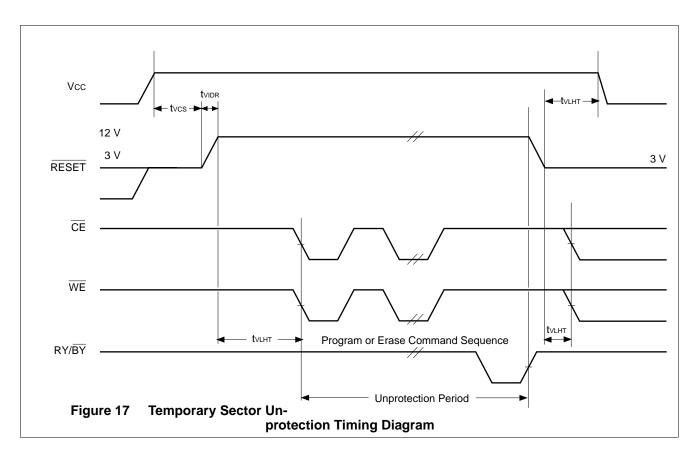


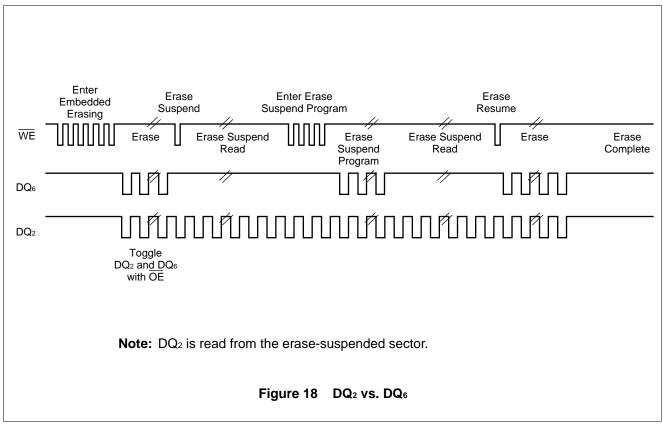


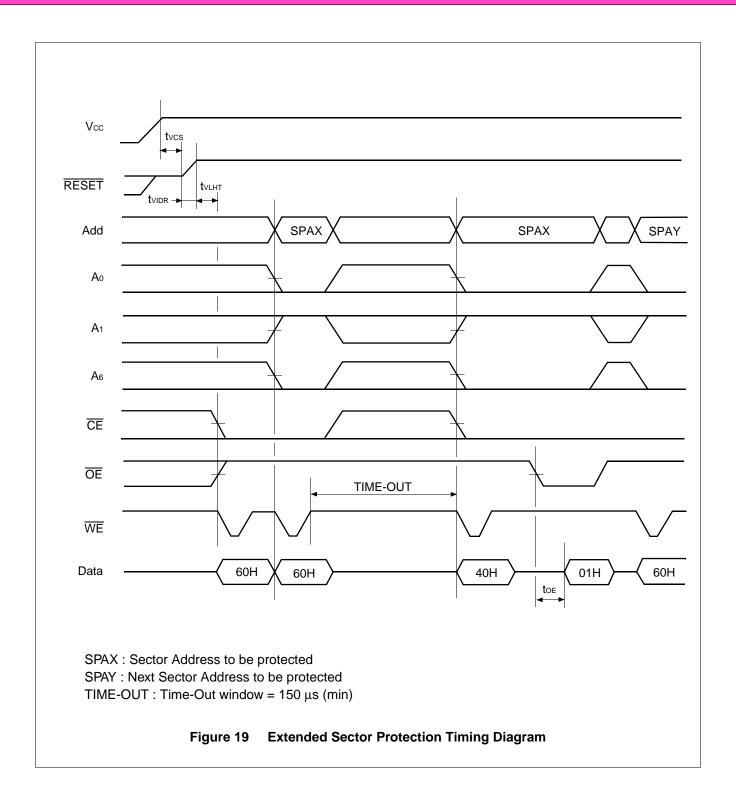


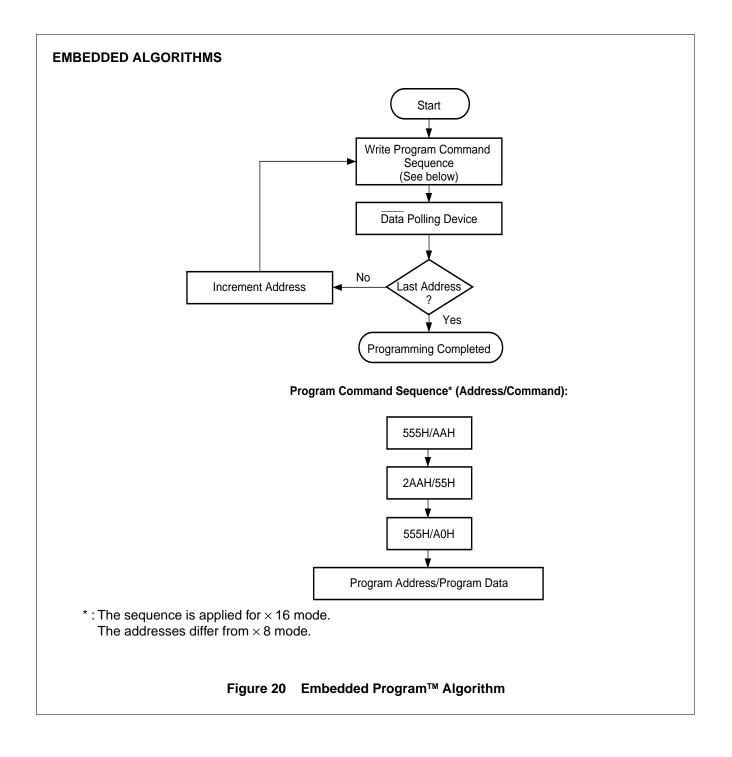


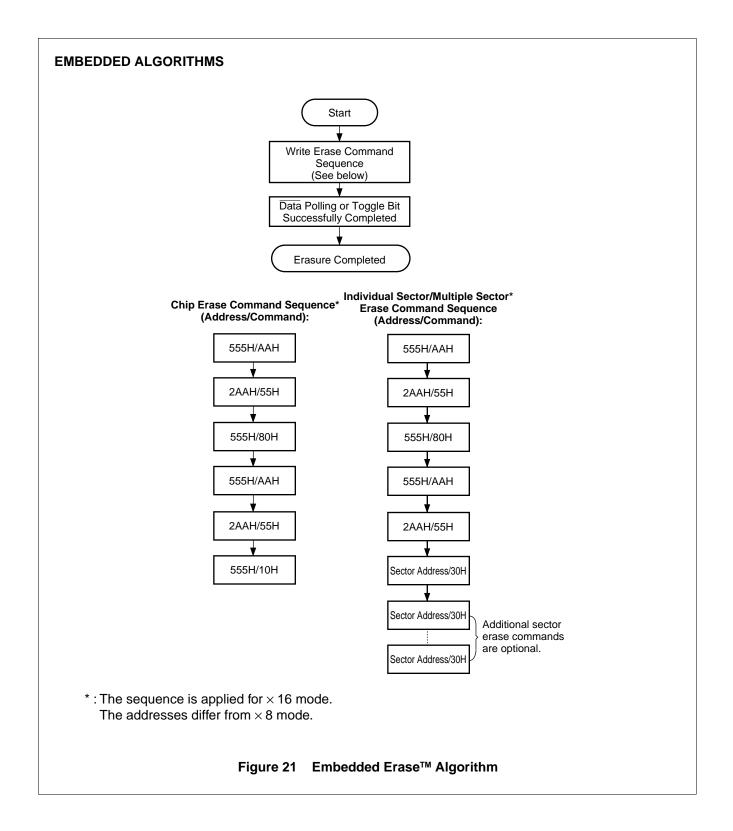


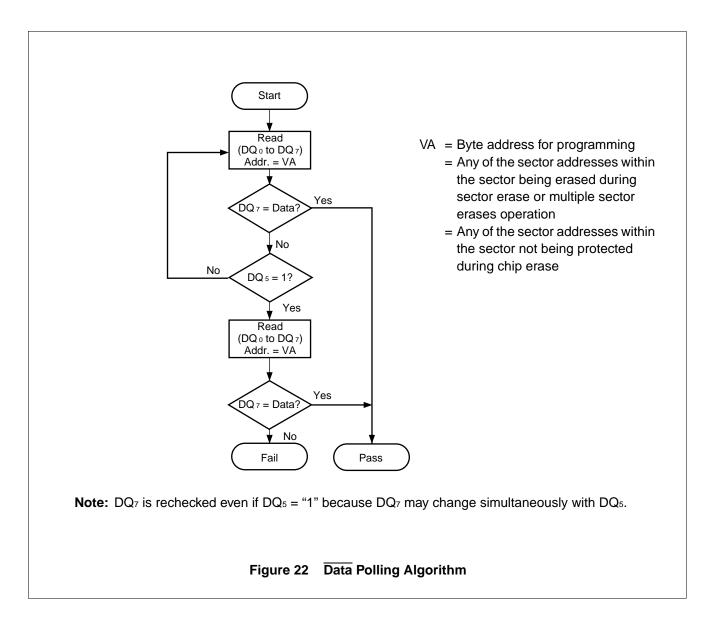


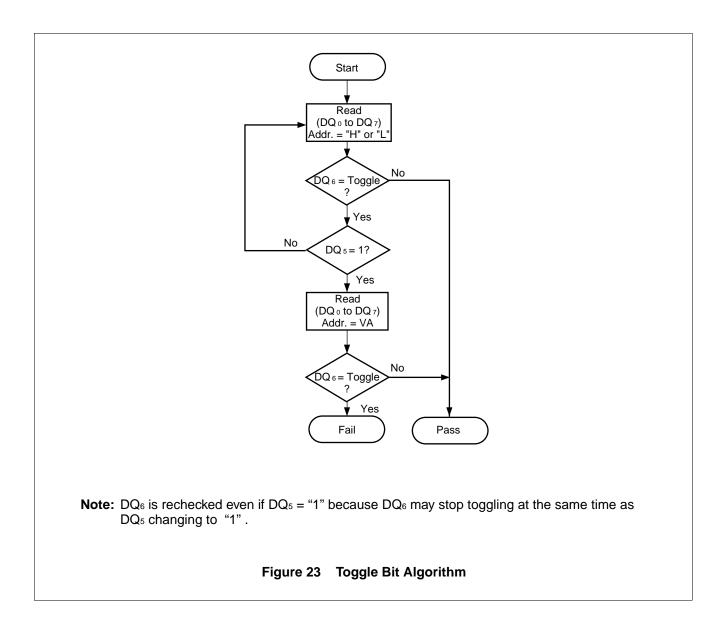


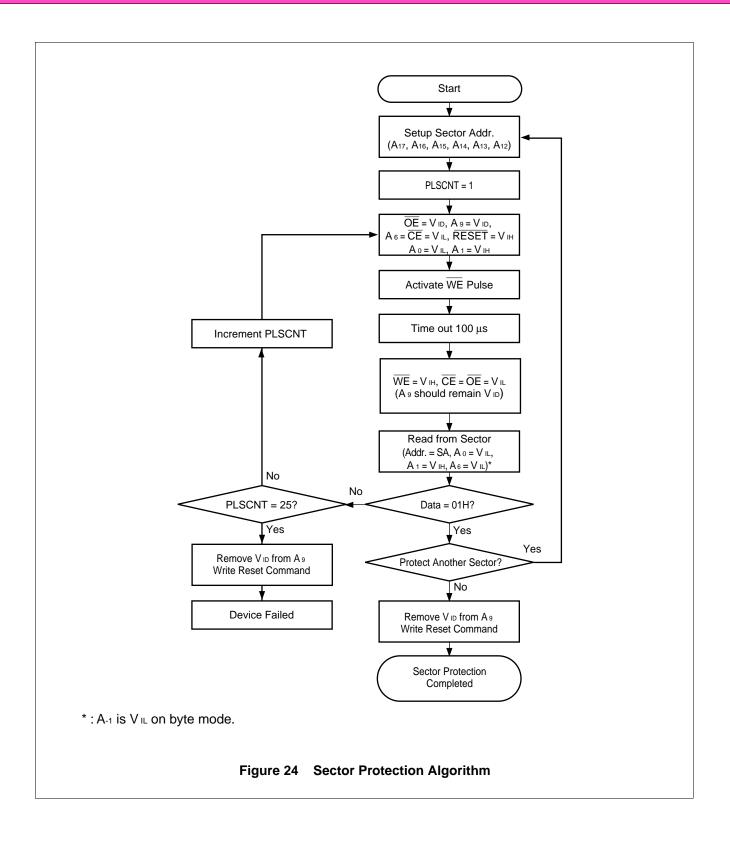


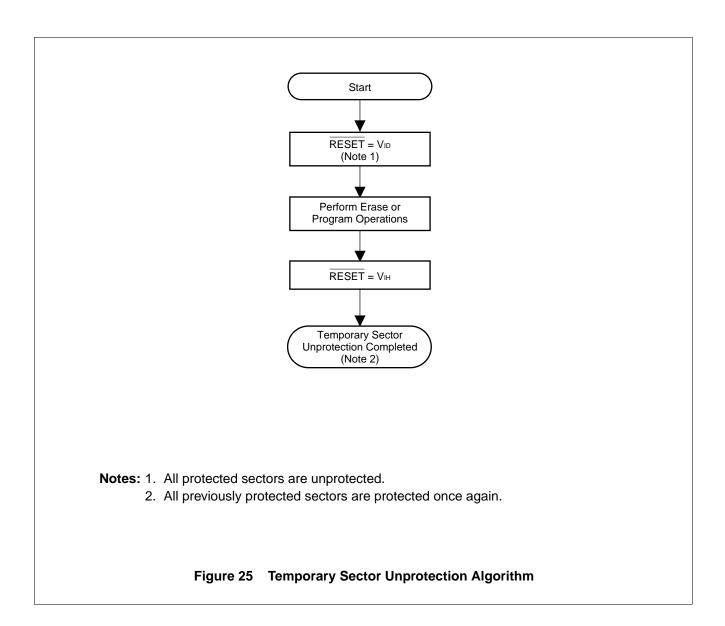


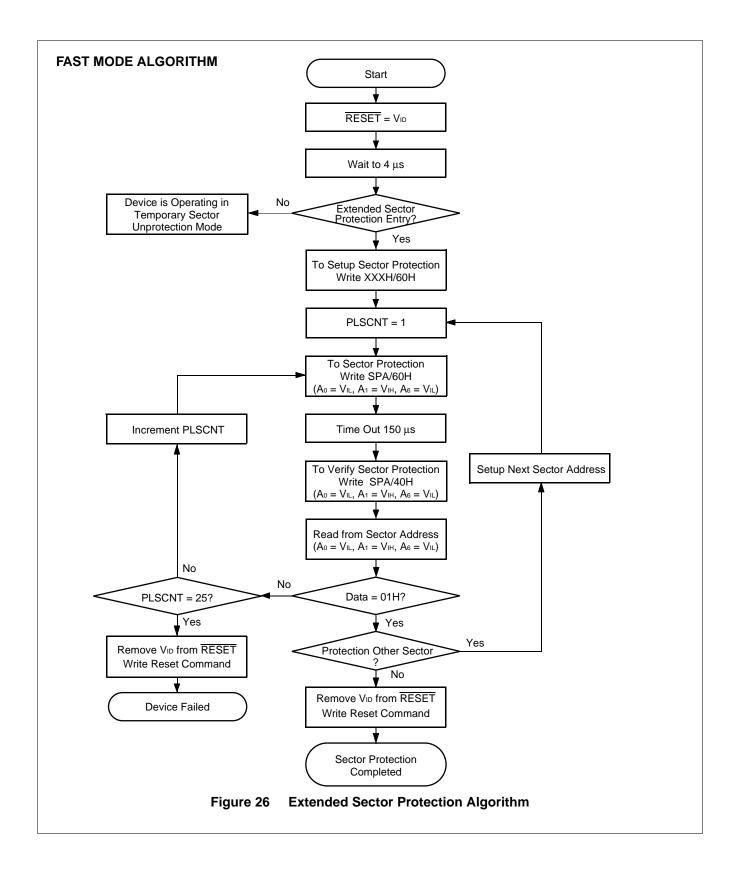


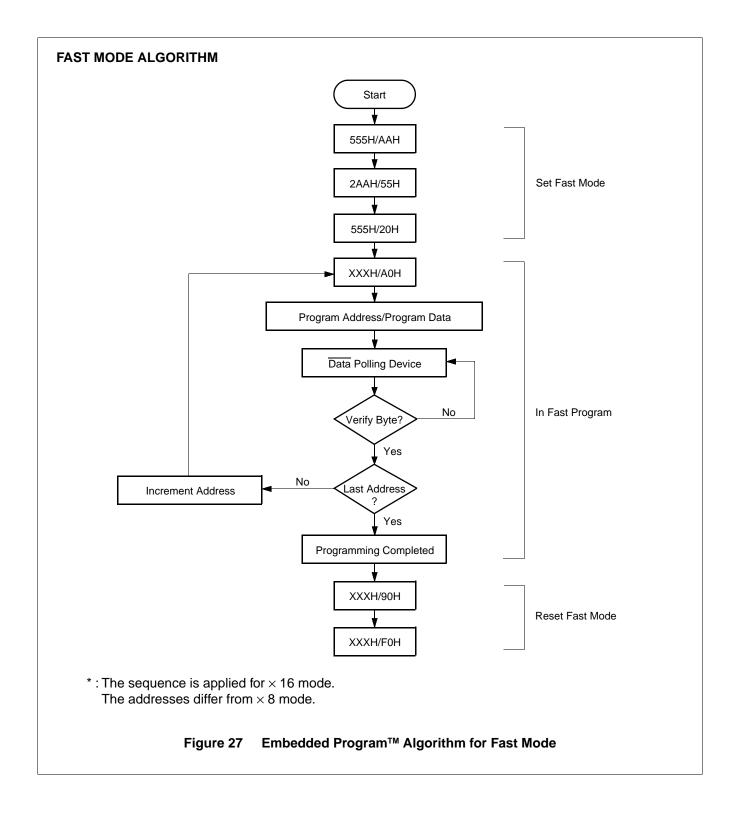












### **■ ERASE AND PROGRAMMING PERFORMANCE**

Parameter	Limits			Unit	Comments	
Farameter	Min.	Тур.	Max.	Ullit	Comments	
Sector Erase Time	_	1	10	sec	Excludes programming time prior to erasure	
Word Programming Time	_	16	360	μs	Excludes system-level	
Byte Programming Time	_	8	300	μs	overhead	
Chip Programming Time	_	4.2	12.5	sec	Excludes system-level overhead	
Program/Erase Cycle	100,000	_	_	cycles	_	

### ■ TSOP(I) PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Unit
Cin	Input Capacitance	V <sub>IN</sub> = 0	7.5	9	pF
Соит	Output Capacitance	Vоит = 0	8	10	pF
C <sub>IN2</sub>	Control Pin Capacitance	Vin = 0	9.5	12.5	pF

Note: Test conditions T<sub>A</sub> = 25°C, f = 1.0 MHz

### **■ SOP PIN CAPACITANCE**

Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Unit
Cin	Input Capacitance	V <sub>IN</sub> = 0	7.5	9	pF
Соит	Output Capacitance	Vоит = 0	8	10	pF
C <sub>IN2</sub>	Control Pin Capacitance	V <sub>IN</sub> = 0	9.5	12.5	pF

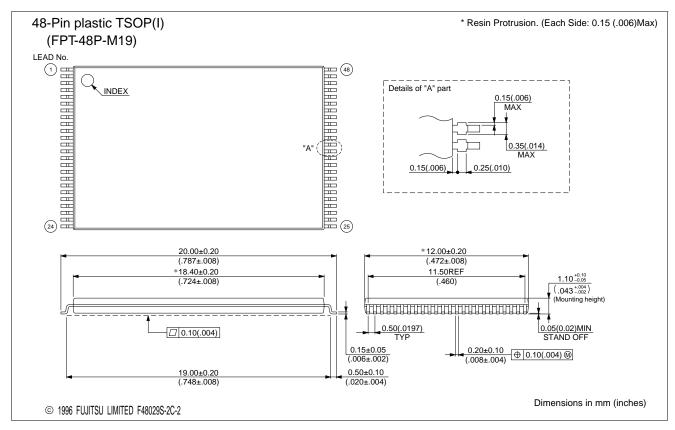
**Note:** Test conditions  $T_A = 25$ °C, f = 1.0 MHz

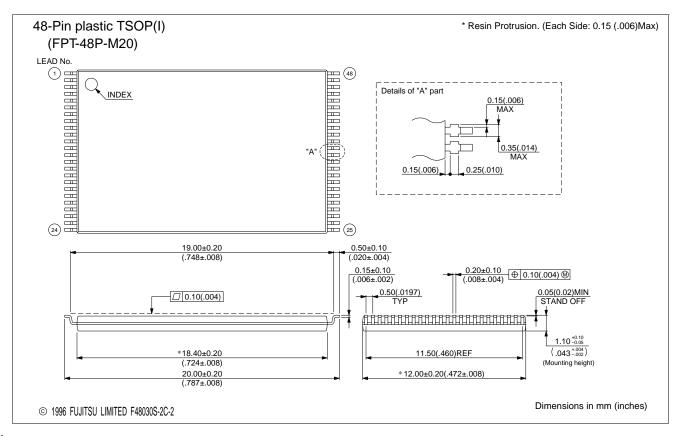
### **■ FBGA PIN CAPACITANCE**

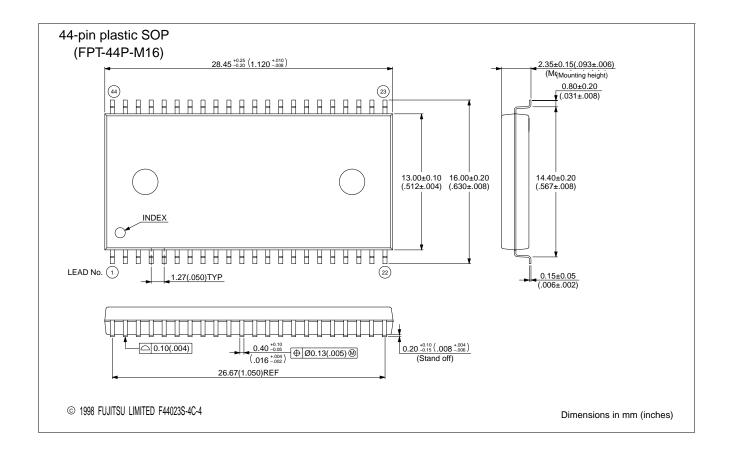
Parameter Symbol	Parameter Description	Test Setup	Тур.	Max.	Unit
Cin	Input Capacitance	V <sub>IN</sub> = 0	7.5	9	pF
Соит	Output Capacitance	Vоит = 0	8	10	pF
C <sub>IN2</sub>	Control Pin Capacitance	V <sub>IN</sub> = 0	9.5	12.5	pF

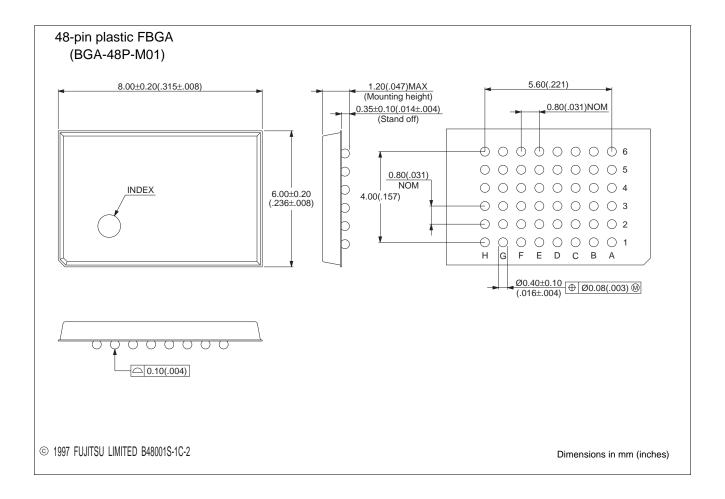
**Note:** Test conditions T<sub>A</sub> = 25°C, f = 1.0 MHz

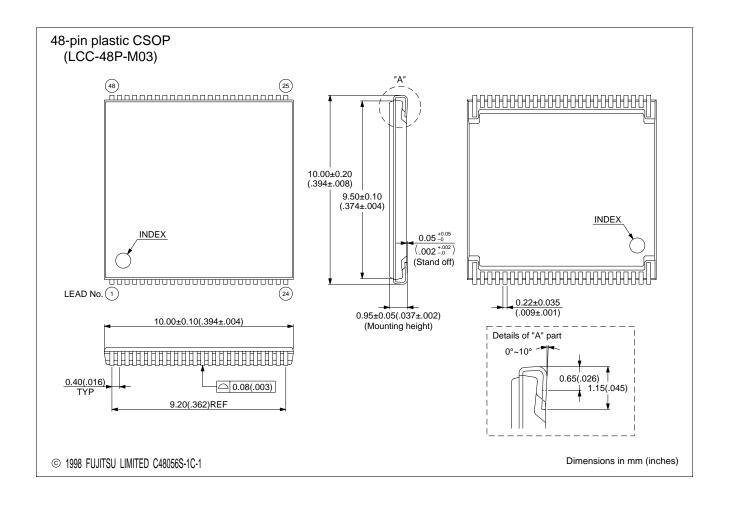
### **■ PACKAGE DIMENSIONS**











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